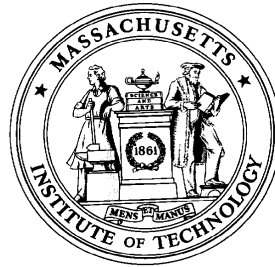


Value Chain Roadmapping for Communications and Media

Prof C. Fine
©MIT 2003



Professor Charles Fine
Massachusetts Institute of Technology
Sloan School of Management
Cambridge, Massachusetts 02142

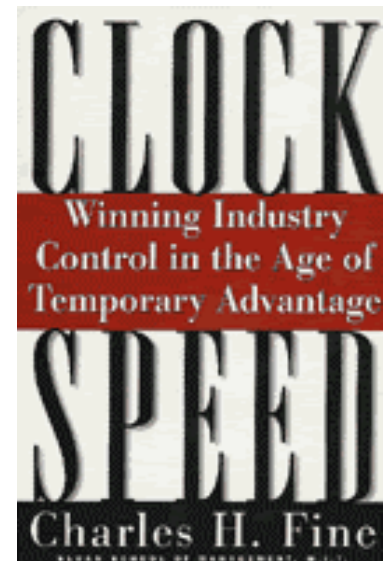
April 2003

charley@mit.edu

<http://web.mit.edu/ctpid/www/people/Fine.html>

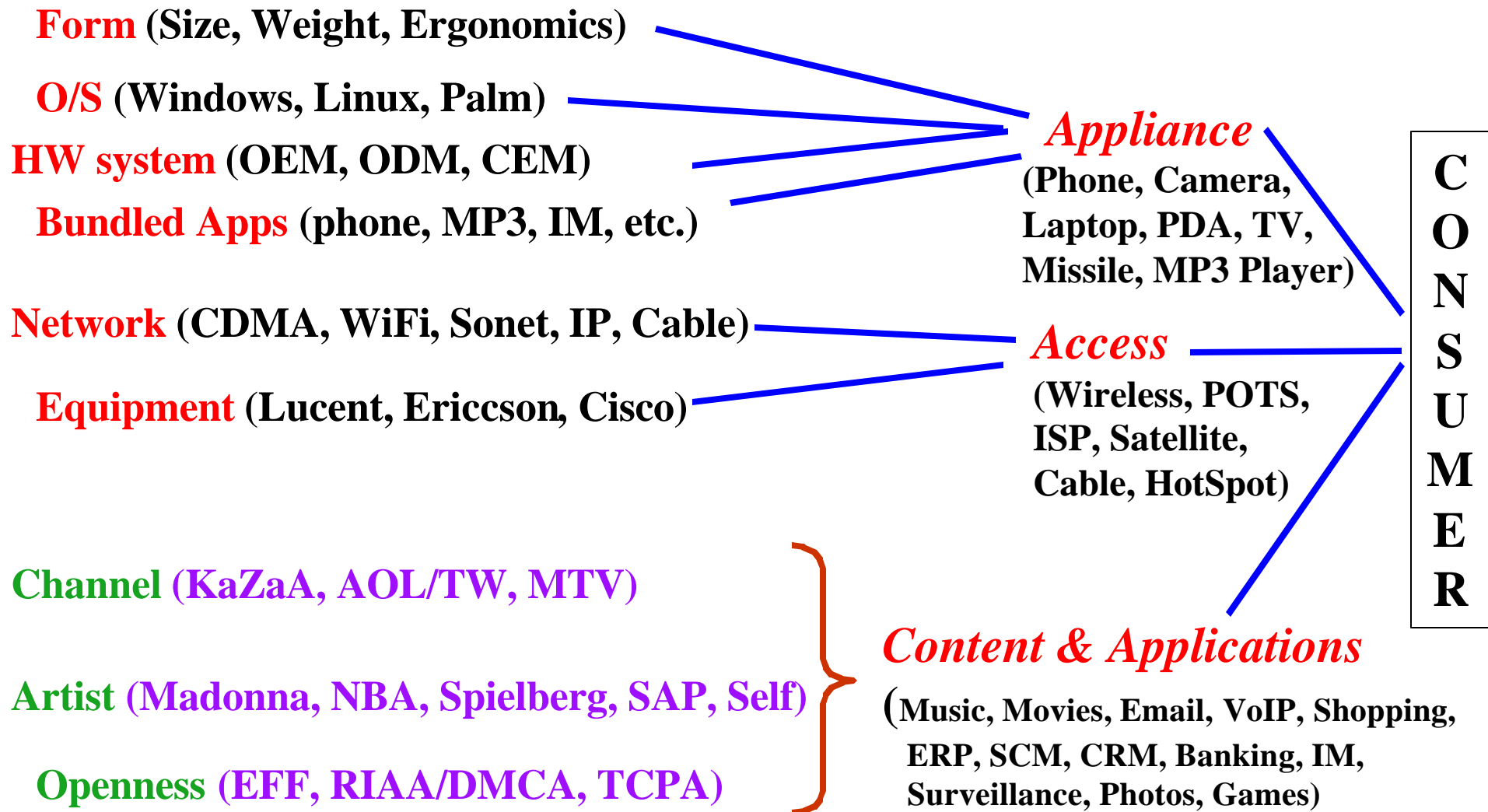
Tel: 1-617-253-3632, Fax: 1-617-253-6720

Excerpts from



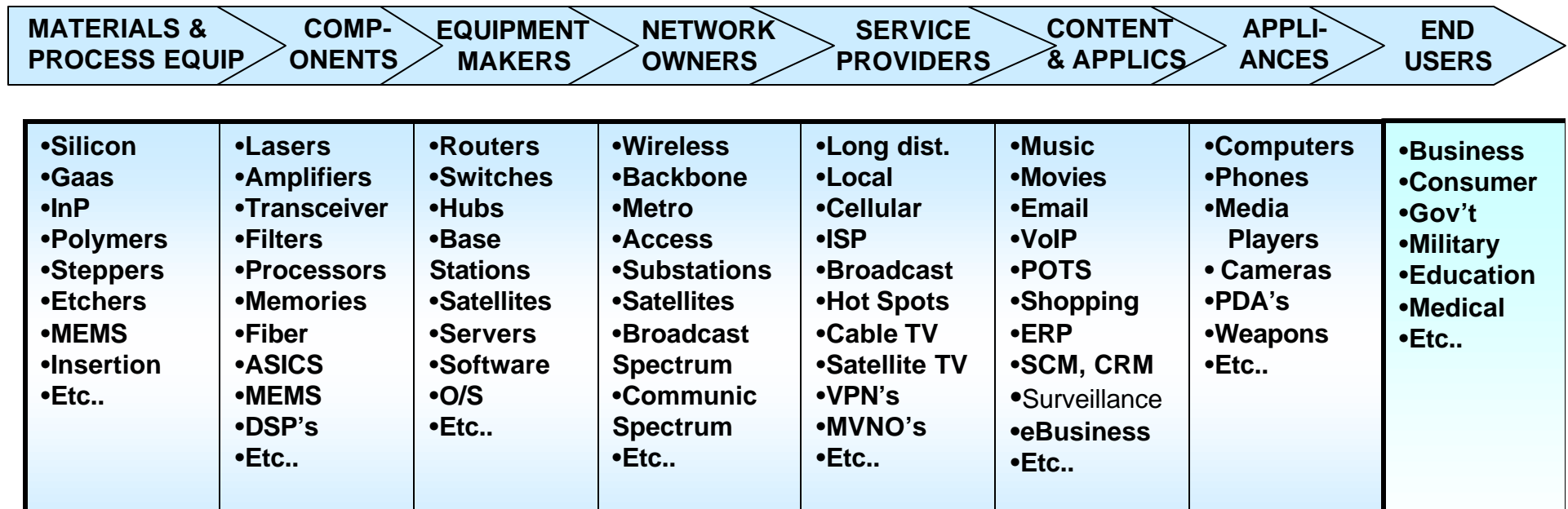
One View (the consumer's) of the Communications Value Chain

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Another View of the Communications Value Chain

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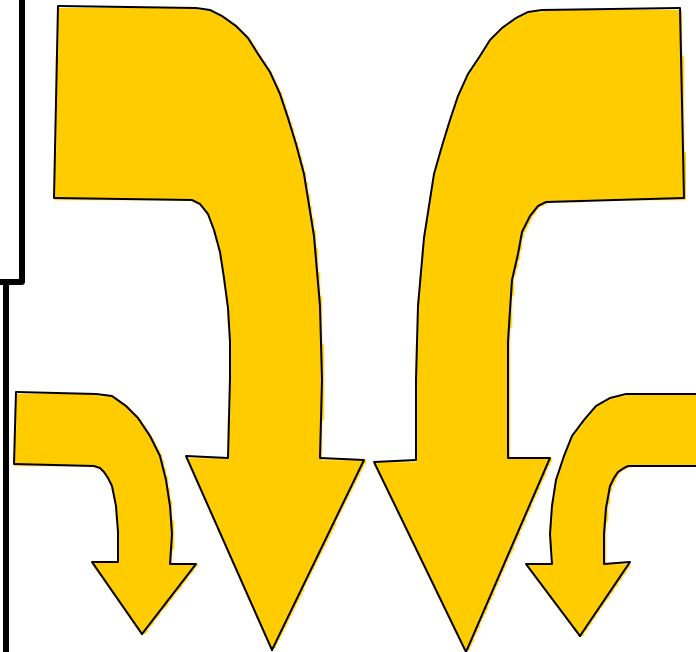


Roadmapping Communications: What are the Premises?

Prof C. Fine
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**Communications
Value Chain is in
ill health**
(ROADKILL
MAPPING?)

**Vertical
disintegration is
the dominant
structure. Silo
execs tend to focus
on their own
narrow slices.
Most industry
consortia are
within-silo.**



**Silos in the value
chain are
interdependent
(integrality).**

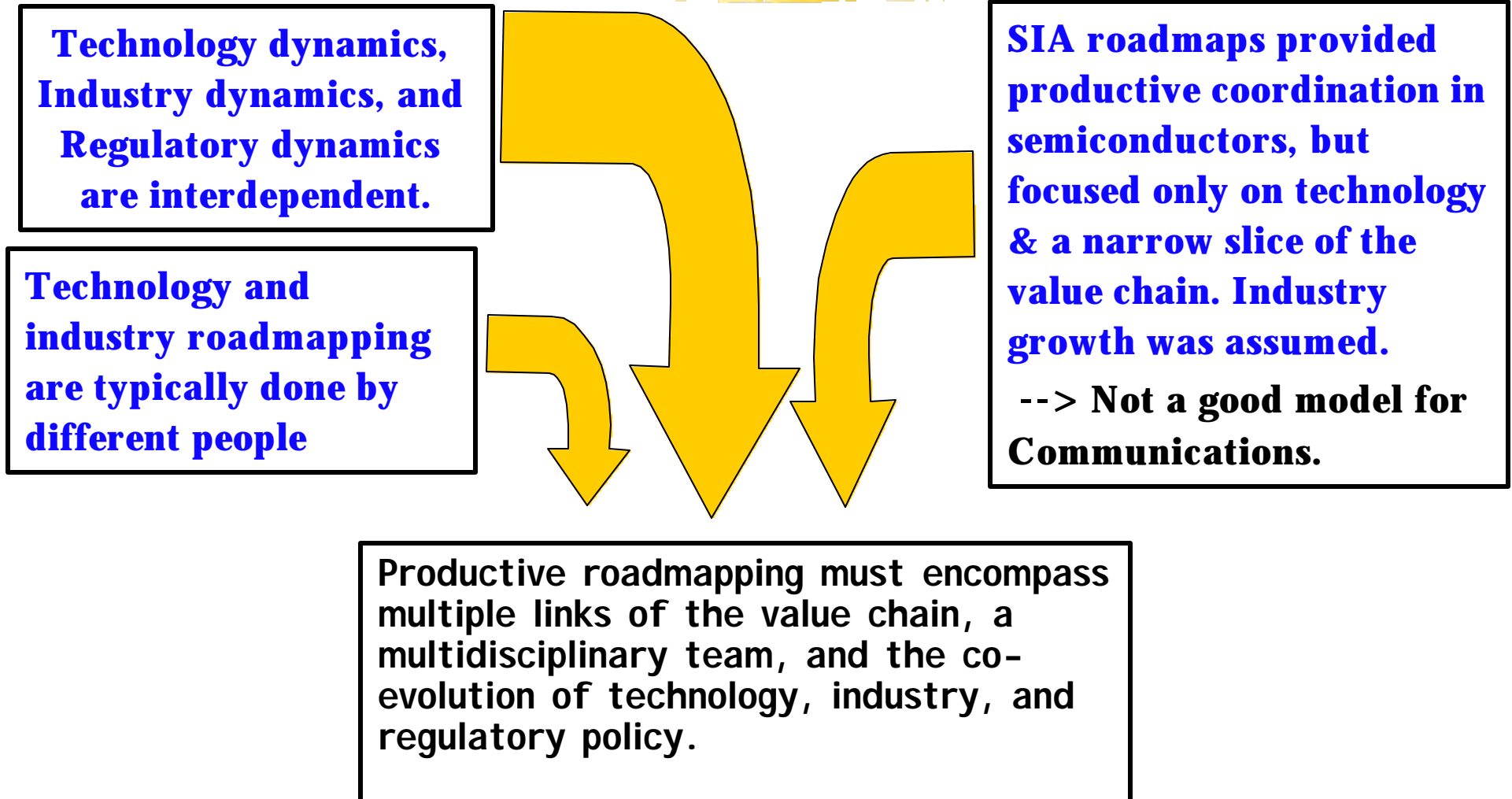
**Absence of
leadership and
coordination across
an interdependent
value chain creates
uncertainty, risk,
and reluctance to
invest.**

**SOME VALUE CHAIN
COORDINATION COULD
SPEED GROWTH.**

**HOW TO ACHIEVE COORDINATION IN
THE ABSENCE OF VERTICAL INTEGRATION?**

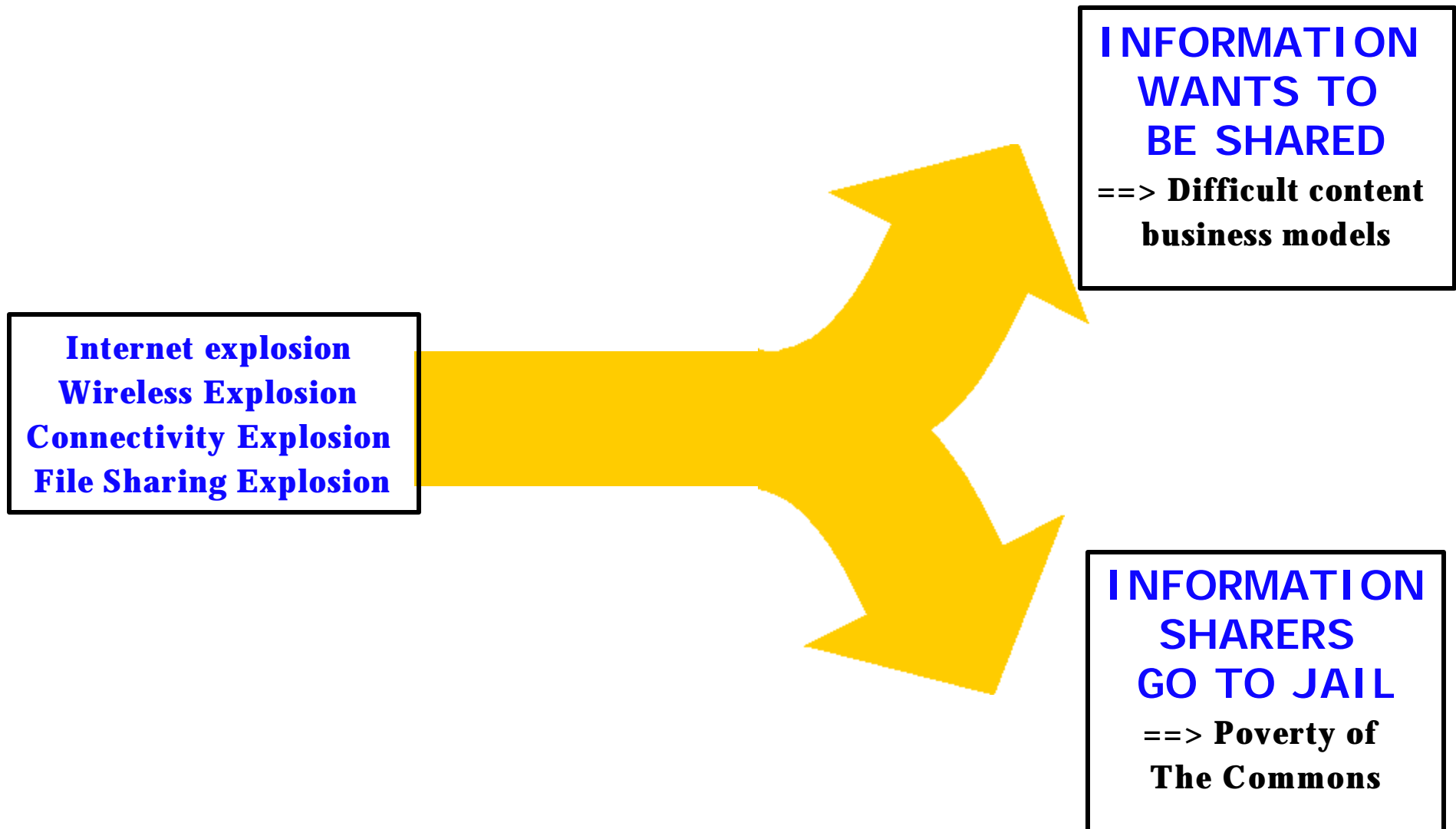
Roadmapping Communications: What are the Premises?

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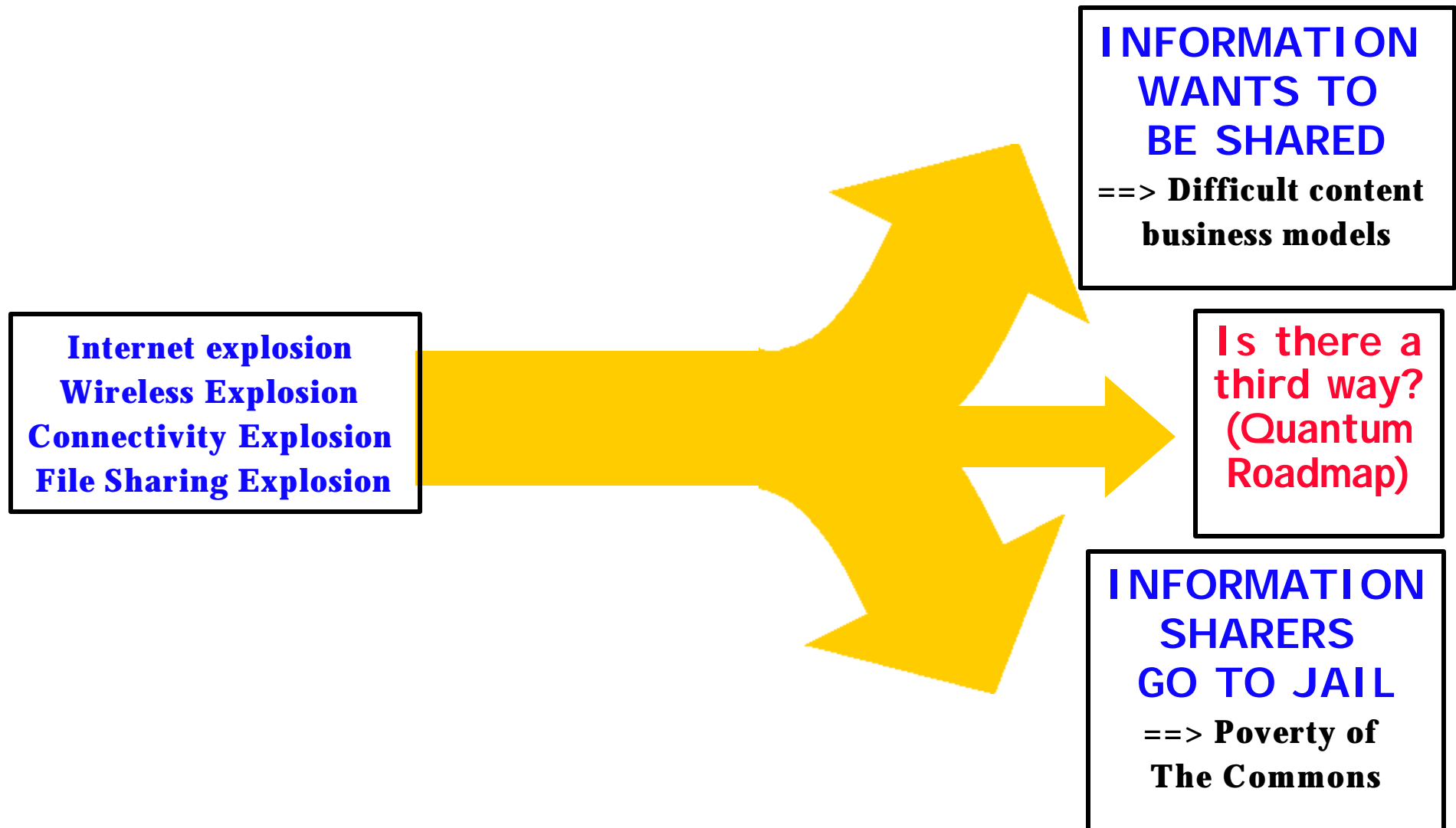
“If you come to a fork in the Road[map], Take it.”
--Yogi Berra

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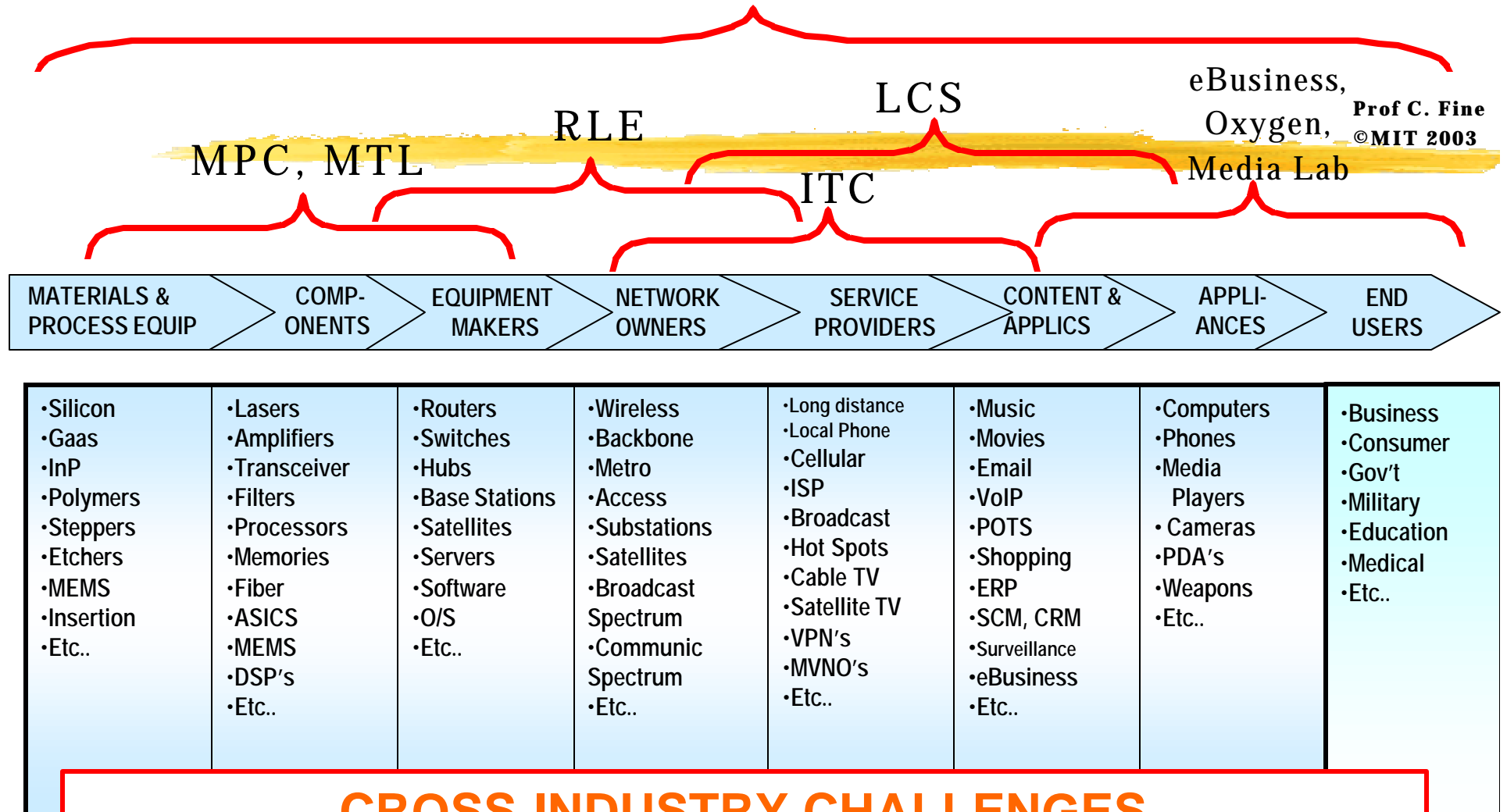
“If you come to a fork in the Road[map], Take it.”
--Yogi Berra

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Proposed MIT Communications Roadmap Consortium

8



CROSS-INDUSTRY CHALLENGES

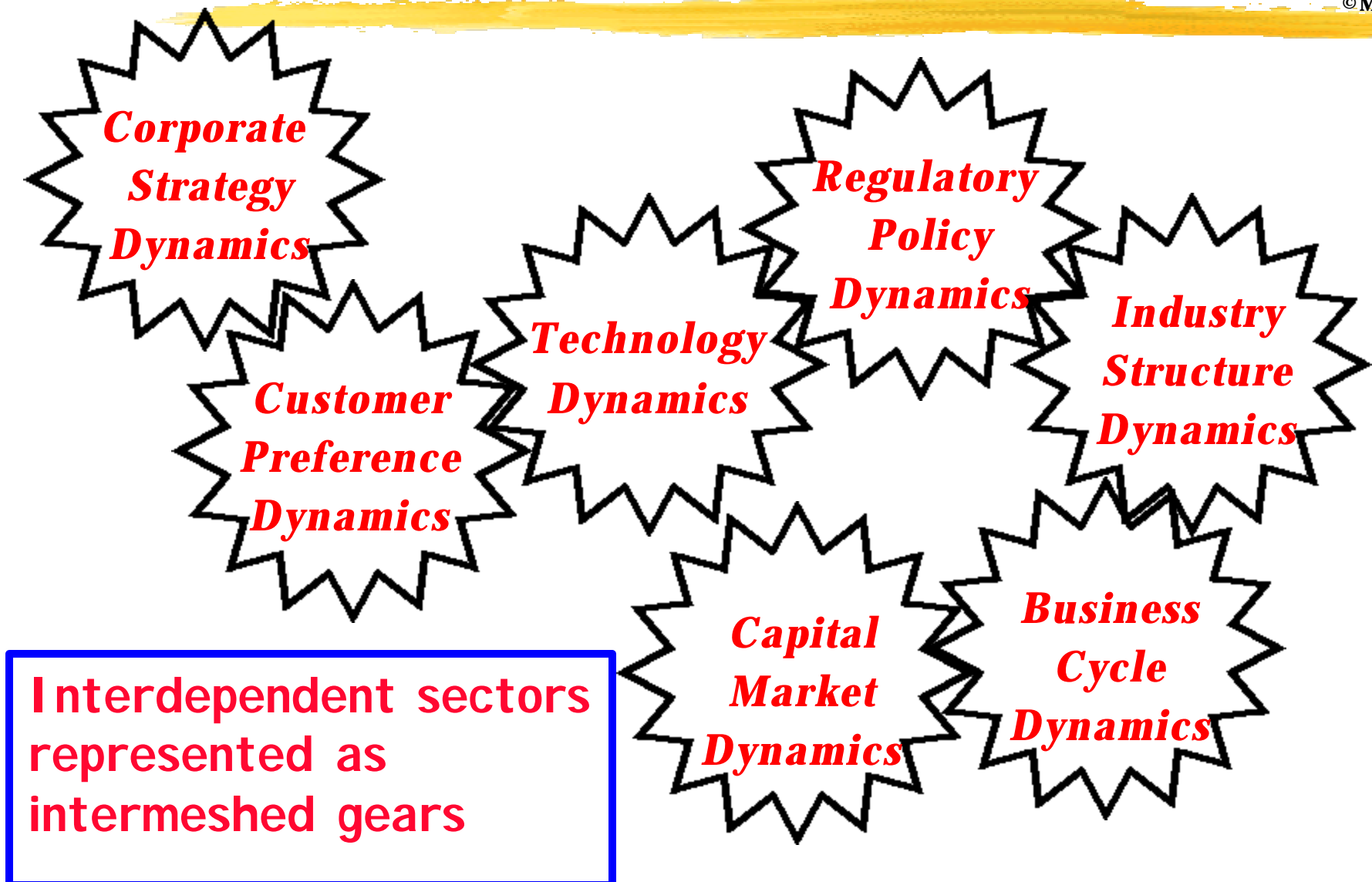
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Access Architecture

Prof. C. Fine, MIT

Dynamic Analysis to Support Industry & Technology Roadmapping

Prof C. Fine
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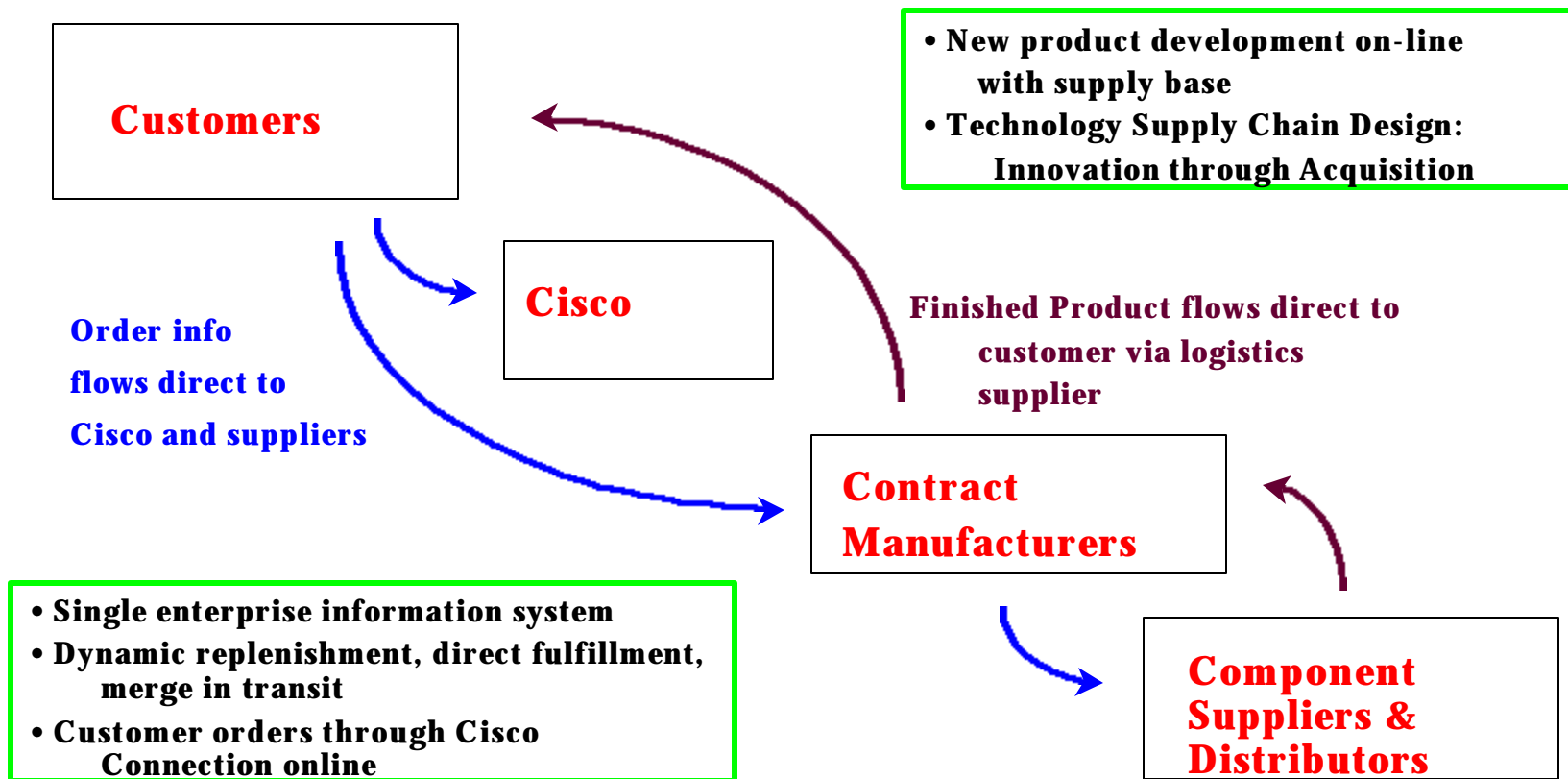
Roadmap Components: Dynamic Analyses

Prof C. Fine
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- **Business cycle dynamics**
(e.g., the bullwhip effect)
- **Industry structure dynamics**
(e.g., double helix in *Clockspeed*)
- 3. Corporate strategy dynamics (e.g., dynamic matching
of customer needs with corporate opportunities)**
- 4. Customer Preference Dynamics**
- 5. Technology dynamics (e.g., the Semiconductor
Industry Assoc. roadmap built around Moore's law)**
- 6. Regulatory Policy Dynamics**
(Cross-National, Cross Sector)
- 7. Capital Markets Dynamics**

Cisco's End-to-End Integration for its Fulfillment Supply Chain

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Basic Design Principle: Arm's length Relationship with Fulfillment Chain Partners

Cisco's Strategy for Technology Supply Chain Design

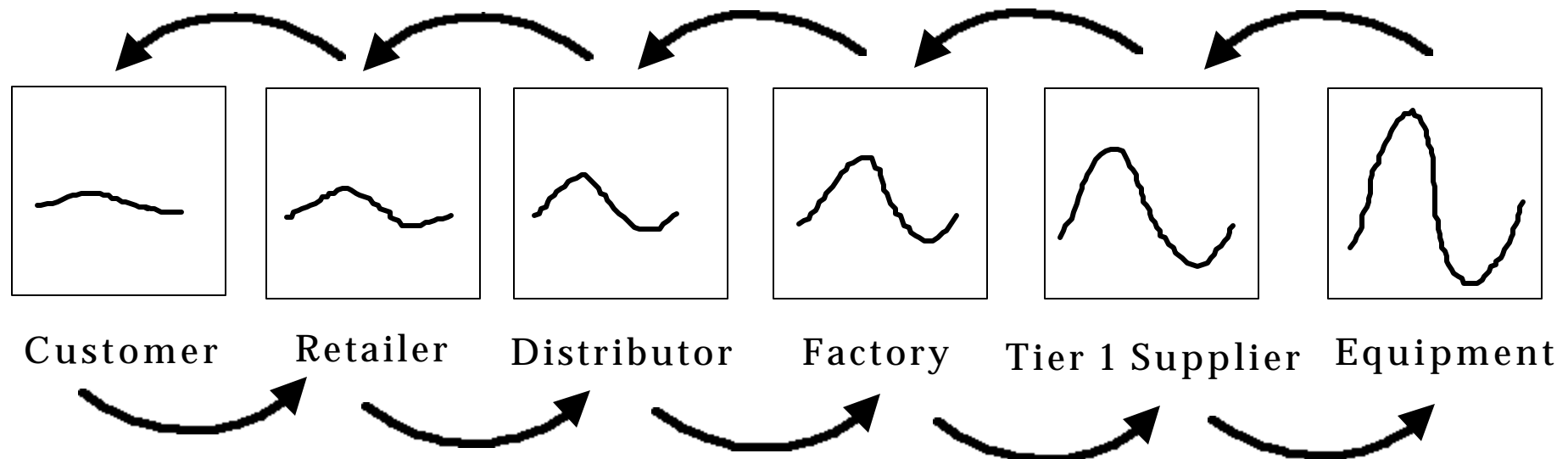
Prof C. Fine
©MIT 2003

- Integrate technology around the router to be a communications network provider.
- 2. Leverage acquired technology with
 - sales muscle and reach
 - end-to-end IT
 - outsourced manufacturing
 - market growth
- 3. Leverage venture capital to supply R&D

**Basic Design Principle: Acquisition
Relationship with Technology Chain Partners**

Volatility Amplification in the Supply Chain: *"The Bullwhip Effect"*

Prof C. Fine
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Information lags
 Delivery lags
 Over- and underordering
 Misperceptions of feedback
 Lumpiness in ordering
 Chain accumulations

SOLUTIONS:

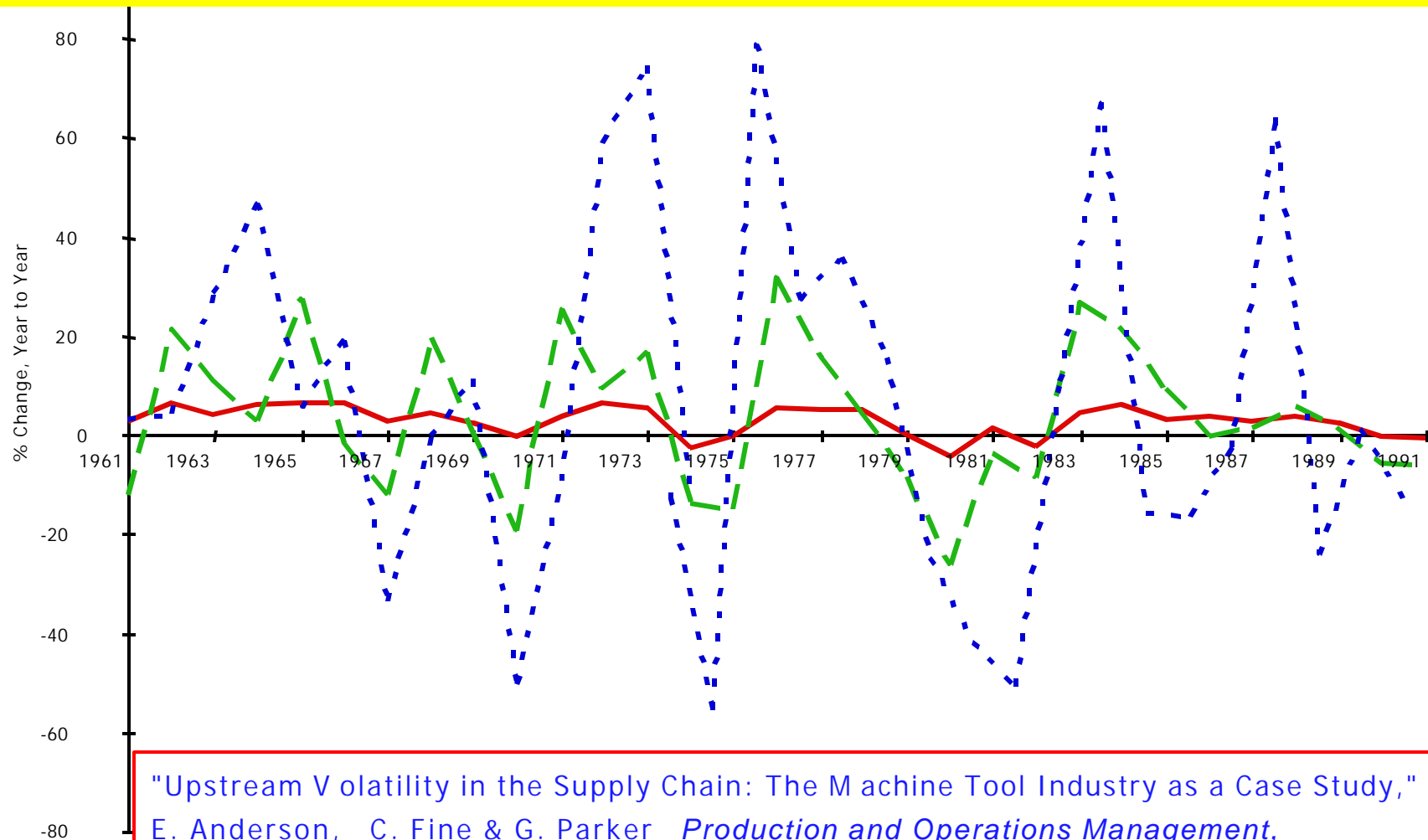
Countercyclical Markets
 Countercyclical Technologies
 Collaborative channel mgmt.
 (Cincinnati Milacron & Boeing)

Supply Chain Volatility Amplification: Machine Tools at the tip of the Bullwhip

— % Chg. GDP — % Chg. Vehicle Production Index - - - % Chg. Net New Orders Machine Tool Industry

Prof C. Fine

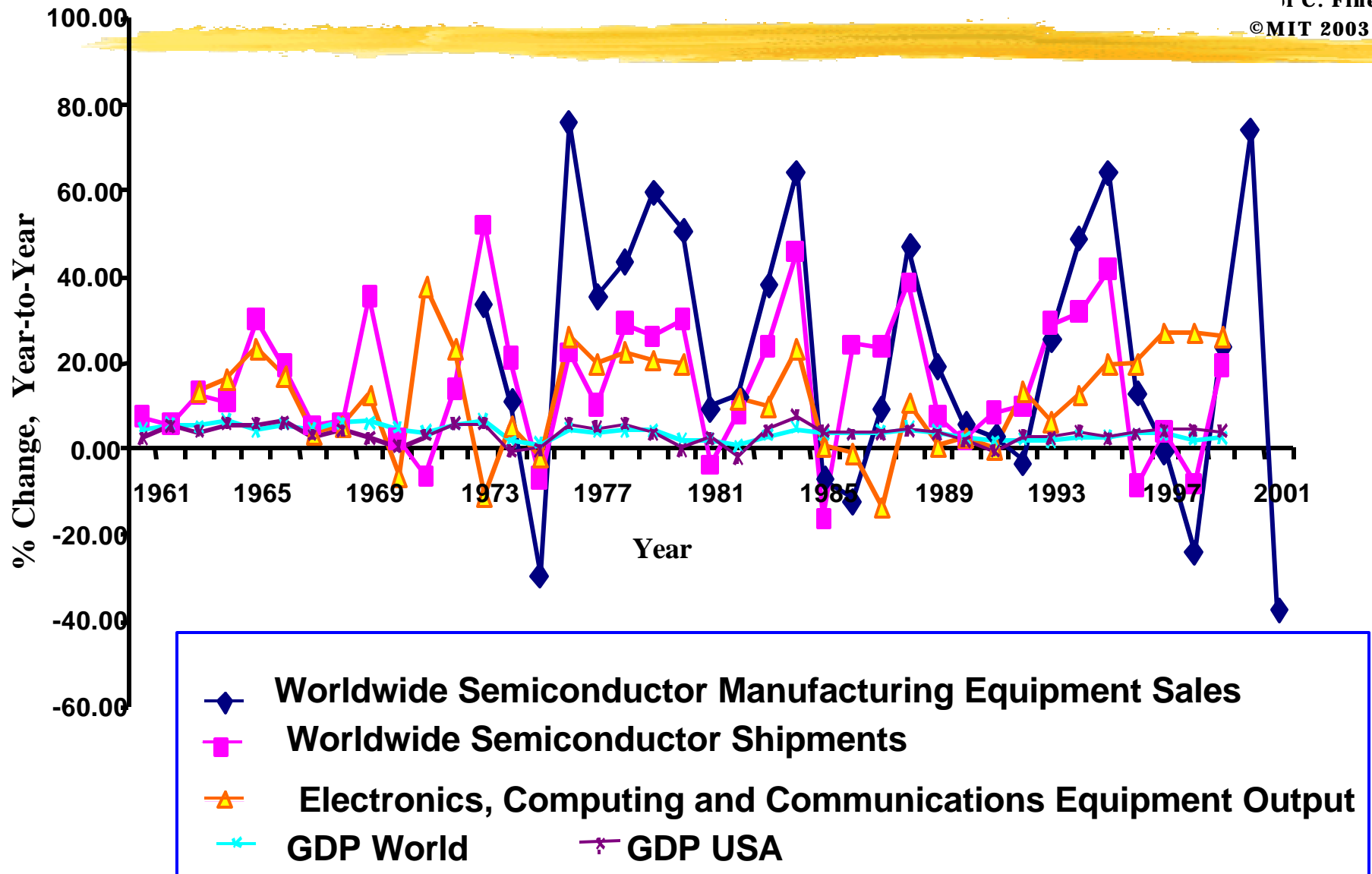
“We are experiencing a 100-year flood.” J. Chambers, 4/16/01



"Upstream Volatility in the Supply Chain: The Machine Tool Industry as a Case Study,"
E. Anderson, C. Fine & G. Parker *Production and Operations Management*,
Vol. 9, No. 3, Fall 2000, pp. 239-261.

Volatility in the Electronics & Semiconductors Supply Chain

of C. Fine
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LESSONS FROM A FRUIT FLY: *CISCO SYSTEMS*

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- KNOW YOUR LOCATION IN THE VALUE CHAIN
- 2. UNDERSTAND THE DYNAMICS
OF VALUE CHAIN FLUCTUATIONS
- 3. THINK CAREFULLY ABOUT THE ROLE
OF VERTICAL COLLABORATIVE RELATIONSHIPS
- 4. INFORMATION AND LOGISTICS SPEED DO NOT
REPEAL BUSINESS CYCLES OR THE BULLWHIP.

Bonus Question:

How does clockspeed impact volatility?

Roadmap Components: Dynamic Analyses

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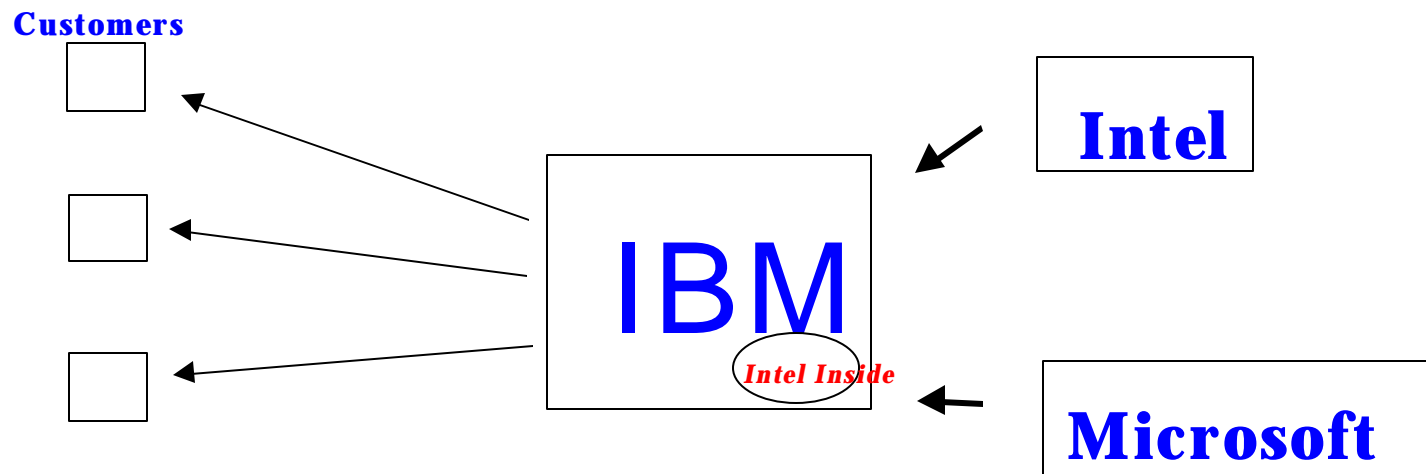
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Industry Assoc. roadmap built around Moore's law)
- 6. **Regulatory Policy Dynamics**
(Cross-National, Cross Sector)

The Strategic Leverage of Value Chain Design:

Who let Intel Inside?

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1980: IBM designs a product, a process, & a value chain



The Outcome:

A phenomenally successful product design

A disastrous value chain design (for IBM)

LESSONS FROM A FRUIT FLY: *THE PERSONAL COMPUTER*

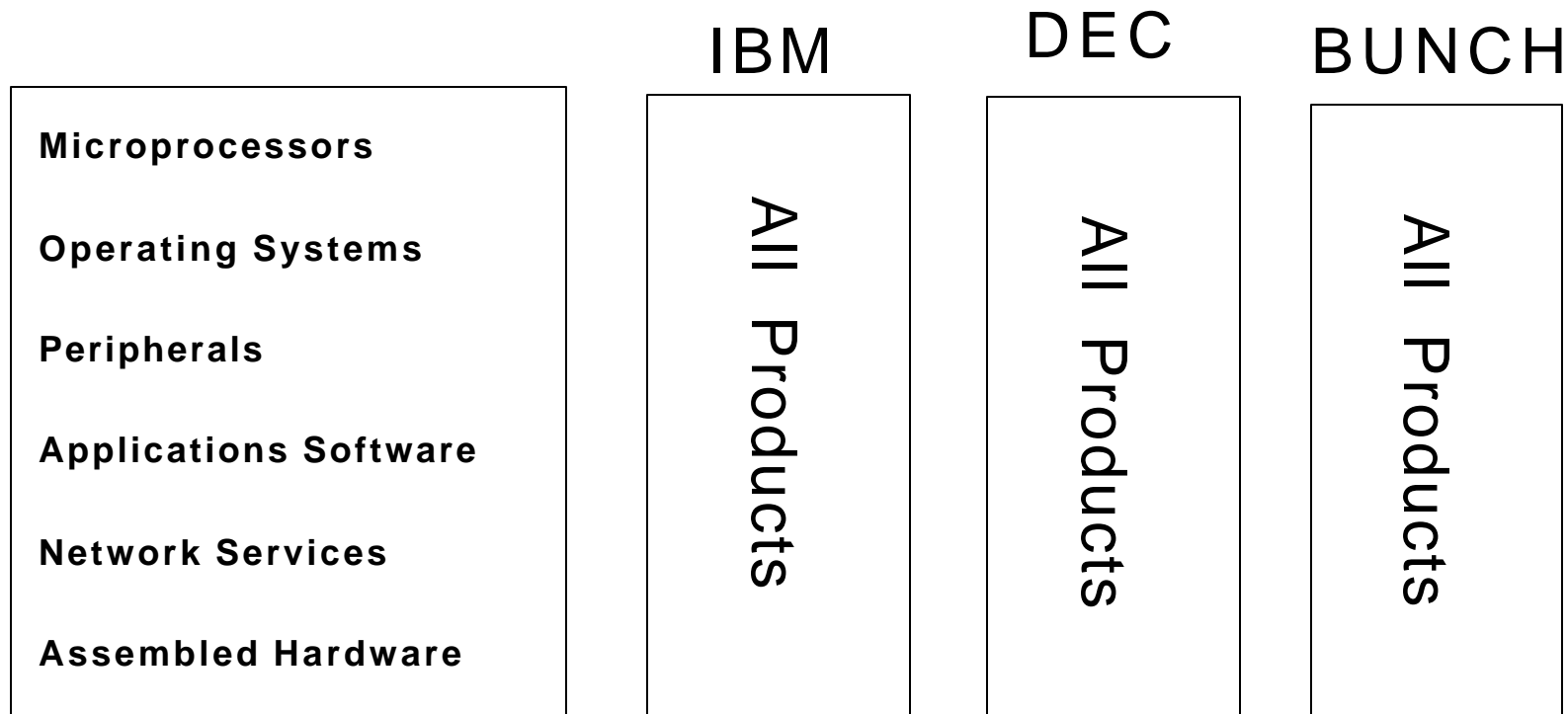
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1. BEWARE OF *INTEL INSIDE*
(Regardless of your industry)
2. MAKE/BUY IS **NOT** ABOUT WHETHER IT IS
TWO CENTS CHEAPER OR *TWO DAYS FASTER*
TO **OUTSOURCE** VERSUS **INSOURCE**.
- DEVELOPMENT PARTNERSHIP DESIGN CAN
DETERMINE THE FATE OF **COMPANIES** AND
INDUSTRIES, AND OF **PROFIT** AND **POWER**
4. THE LOCUS OF VALUE CHAIN CONTROL
CAN SHIFT IN **UNPREDICTABLE** WAYS

Vertical Industry Structure with *Integral* Product Architecture

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Computer Industry Structure, 1975-85



(A. Grove, Intel; and Farrell, Hunter & Saloner, Stanford)

Horizontal Industry Structure with *Modular* Product Architecture

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Computer Industry Structure, 1985-95

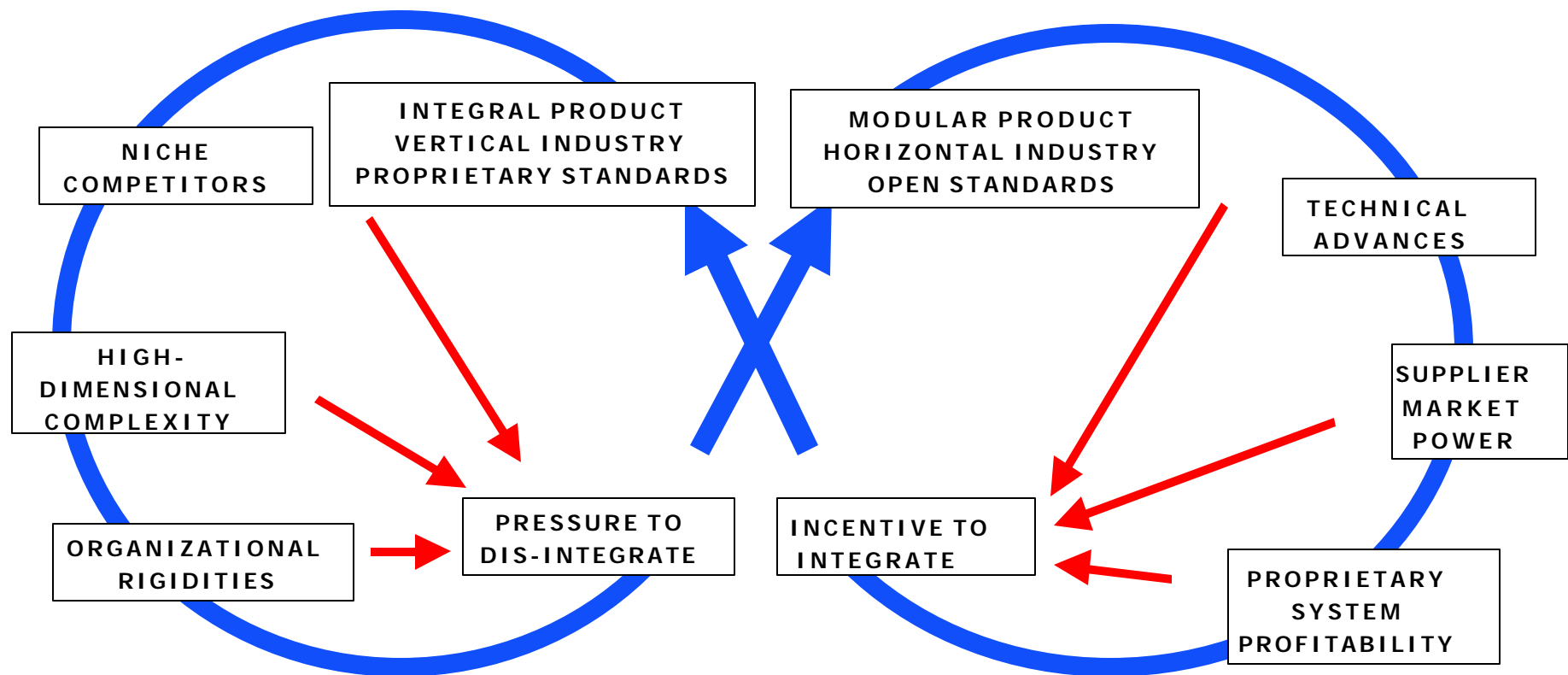
Microprocessors	Intel	Moto	AMD	etc
Operating Systems	Microsoft	Mac	Unix	
Peripherals	HP	Epson	Seagate	etc etc
Applications Software	Microsoft	Lotus	Novell	etc
Network Services	AOL/Netscape	Microsoft	EDS	etc
Assembled Hardware	HP	Compaq	IBM	Dell etc

(A. Grove, Intel; and Farrell, Hunter & Saloner, Stanford)

THE DYNAMICS OF PRODUCT ARCHITECTURE STANDARDS, AND VALUE CHAIN STRUCTURE:

THE DOUBLE HELIX

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Fine & Whitney, "Is the Make/Buy Decision Process a Core Competence?"

Roadmap Components: Dynamic Analyses

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- **Business cycle dynamics**
(e.g., systems dynamics-like models of the bullwhip effect)
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- 4. **Customer Preference Dynamics**
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- 6. **Regulatory Policy Dynamics**
(Cross-National, Cross Sector)

ALL COMPETITIVE ADVANTAGE IS TEMPORARY

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Autos:

Ford in 1920, ***GM*** in 1955, ***Toyota*** in 1990

Computing:

IBM in 1970, ***DEC*** in 1980, ***Wintel*** in 1990

World Dominion:

Greece in 500 BC, ***Rome*** in 100AD, ***G.B.*** in 1800

Sports:

Bruins in 1971, ***Celtics*** in 1986, ***Yankees*** no end

The faster the clockspeed, the shorter the reign

VALUE CHAIN DESIGN:

Three Components

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1. Insourcing/OutSourcing

(The Make/Buy or Vertical Integration Decision)

2. Partner Selection

(Choice of suppliers and partners for the chain)

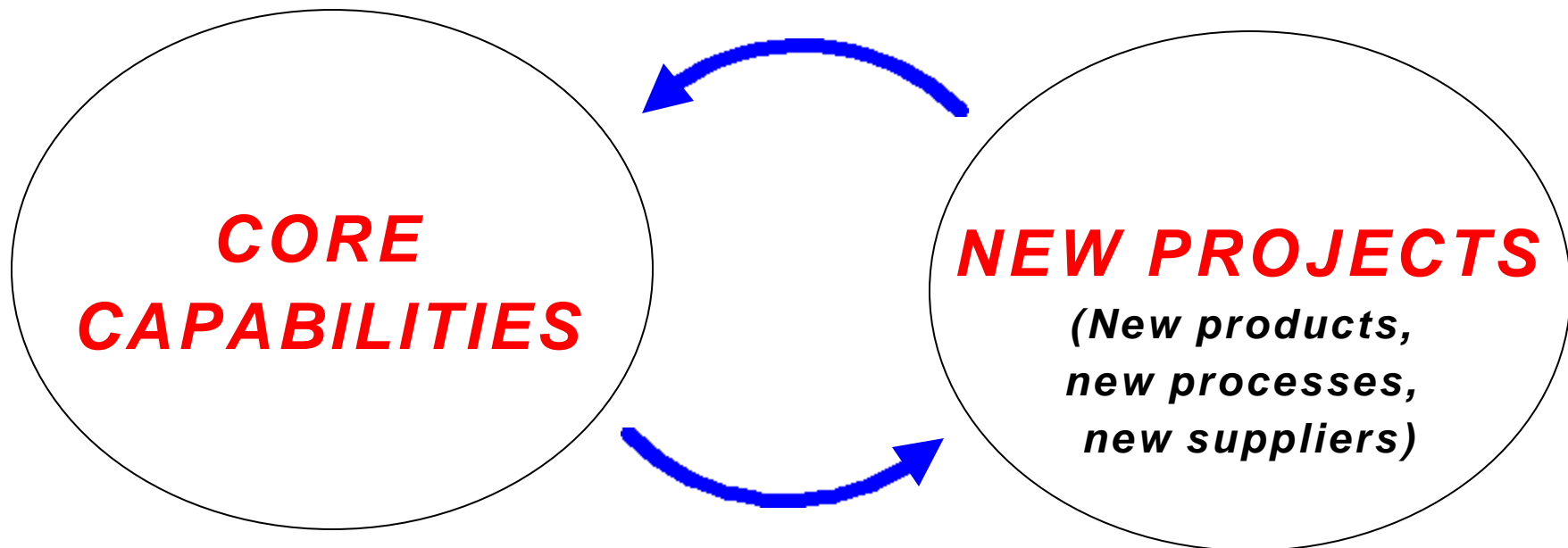
3. The Contractual Relationship

(Arm's length, joint venture, long-term contract, strategic alliance, equity participation, etc.)

Clockspeed drives *Business Strategy Cadence*

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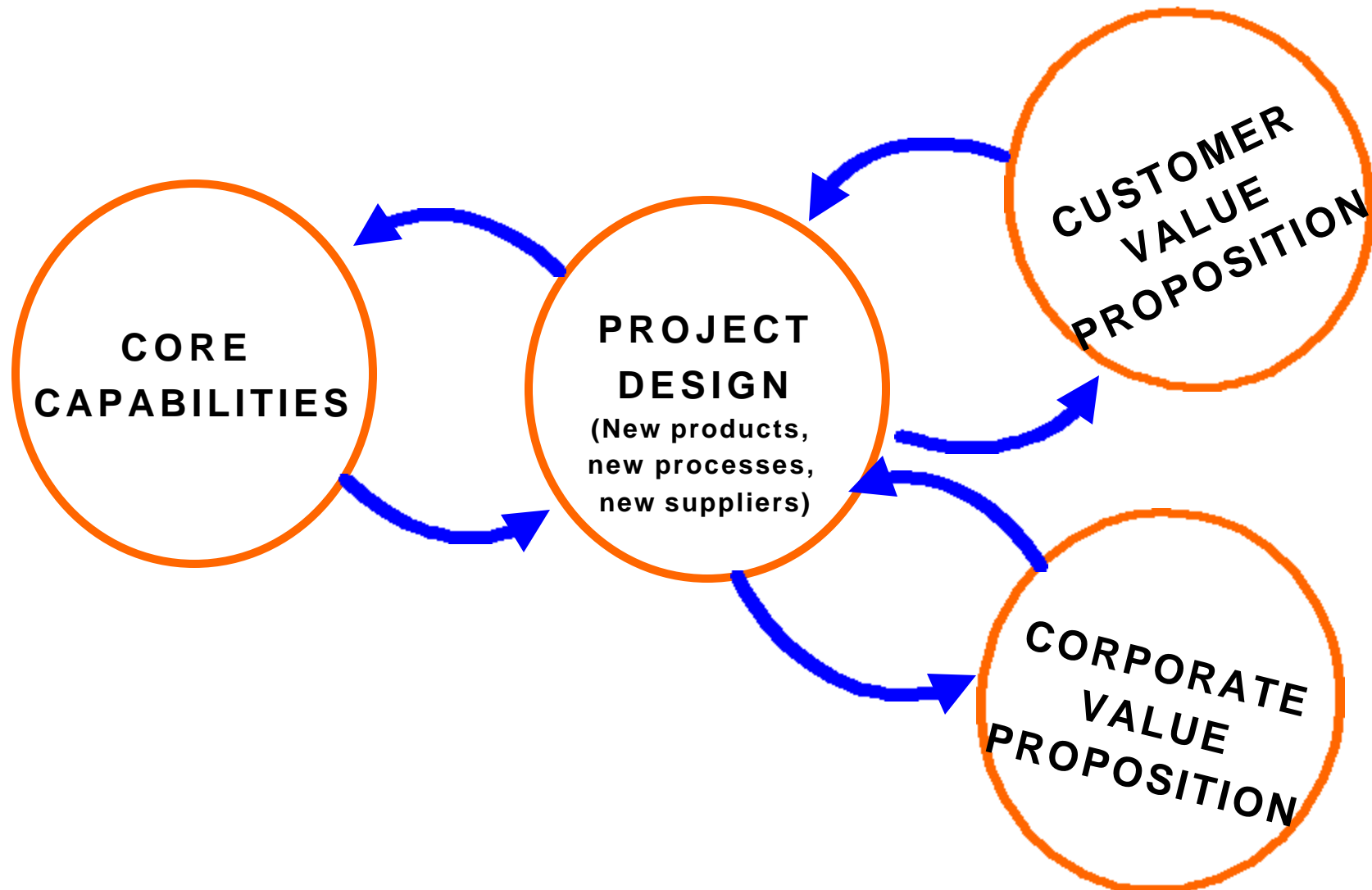
Dynamics between **New Projects** and **Core Capability Development**: **PROJECTS MUST MAKE MONEY AND BUILD CAPABILITIES**



Leonard-Barton, *Wellsprings of Knowledge*

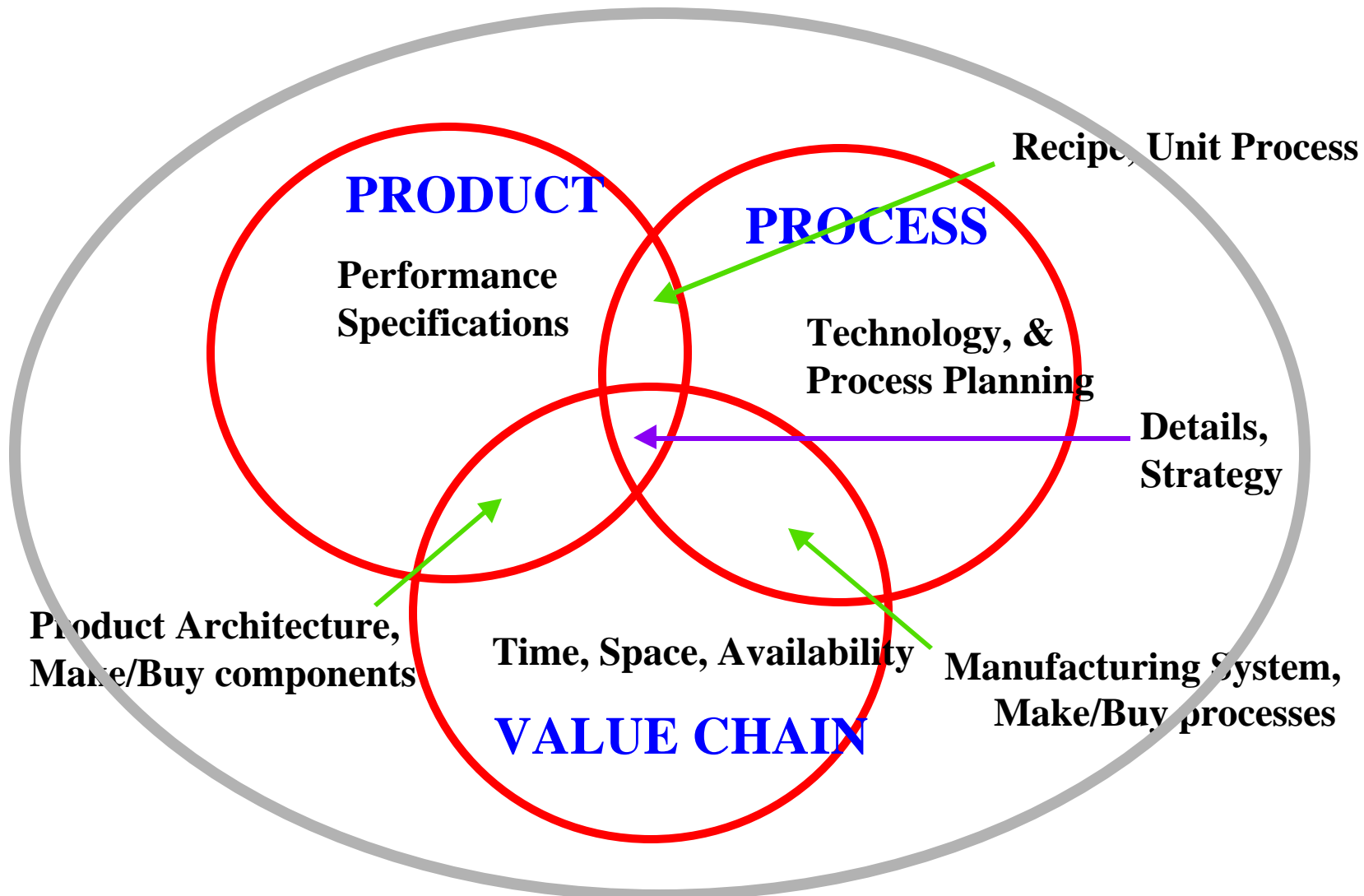
Projects Serve Three Masters: Capabilities, Customers, & Corporate Profit

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IMPLEMENTATION OF **PROJECT DESIGN**: FRAME IT AS 3-D CONCURRENT ENGINEERING

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ARCHITECTURES IN 3-D

INTEGRALITY VS. *MODULARITY*

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Integral product architectures feature
close coupling among the elements

- Elements perform many functions
- Elements are in close spacial proximity
- Elements are tightly synchronized
- Ex: jet engine, airplane wing, microprocessor

Modular product architectures feature
separation among the elements

- Elements are interchangeable
- Elements are individually upgradeable
- Element interfaces are standardized
- System failures can be localized
- Ex: stereo system, desktop PC, bicycle

VALUE CHAIN ARCHITECTURE

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Integral value-chain architecture

features close proximity among its elements

- Proximity metrics: Geographic, Organizational
Cultural, Electronic
- Example: Toyota city
- Example: Ma Bell (AT&T in New Jersey)
- Example: IBM mainframes & Hudson River Valley

Modular value-chain architecture features multiple,
interchangeable supplier and standard interfaces

- Example: Garment industry
- Example: PC industry
- Example: General Motors' global sourcing
- Example: Telephones and telephone service

ALIGNING ARCHITECTURES: BUSINESS SYSTEMS & TECHNOLOGICAL SYSTEMS

Prof C. Fine

2003

BUSINESS SYSTEM/SUPPLY CHAIN ARCHITECTURE

(Geog., Organ., Cultural, Elec.)

INTEGRAL  MODULAR

TECHNOLOGY/PRODUCT ARCHITECTURE

INTEGRAL

MODULAR

Microprocessors
Mercedes
& BMW vehicles

Lucent
Nortel

Polaroid

MSFT Windows

Chrysler
vehicles

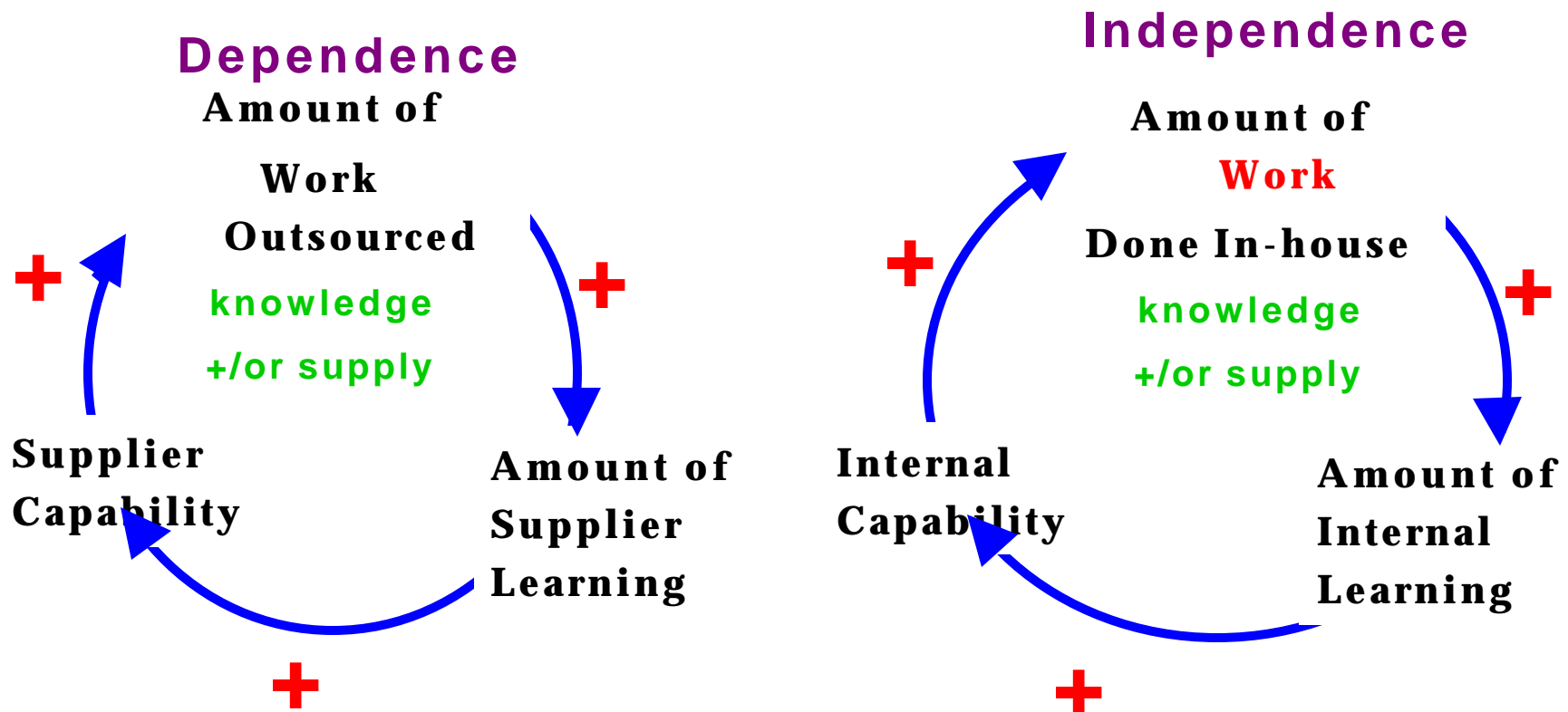
Cisco

Digital Rights/
Music Distribution

Dell PC'S
Bicycles

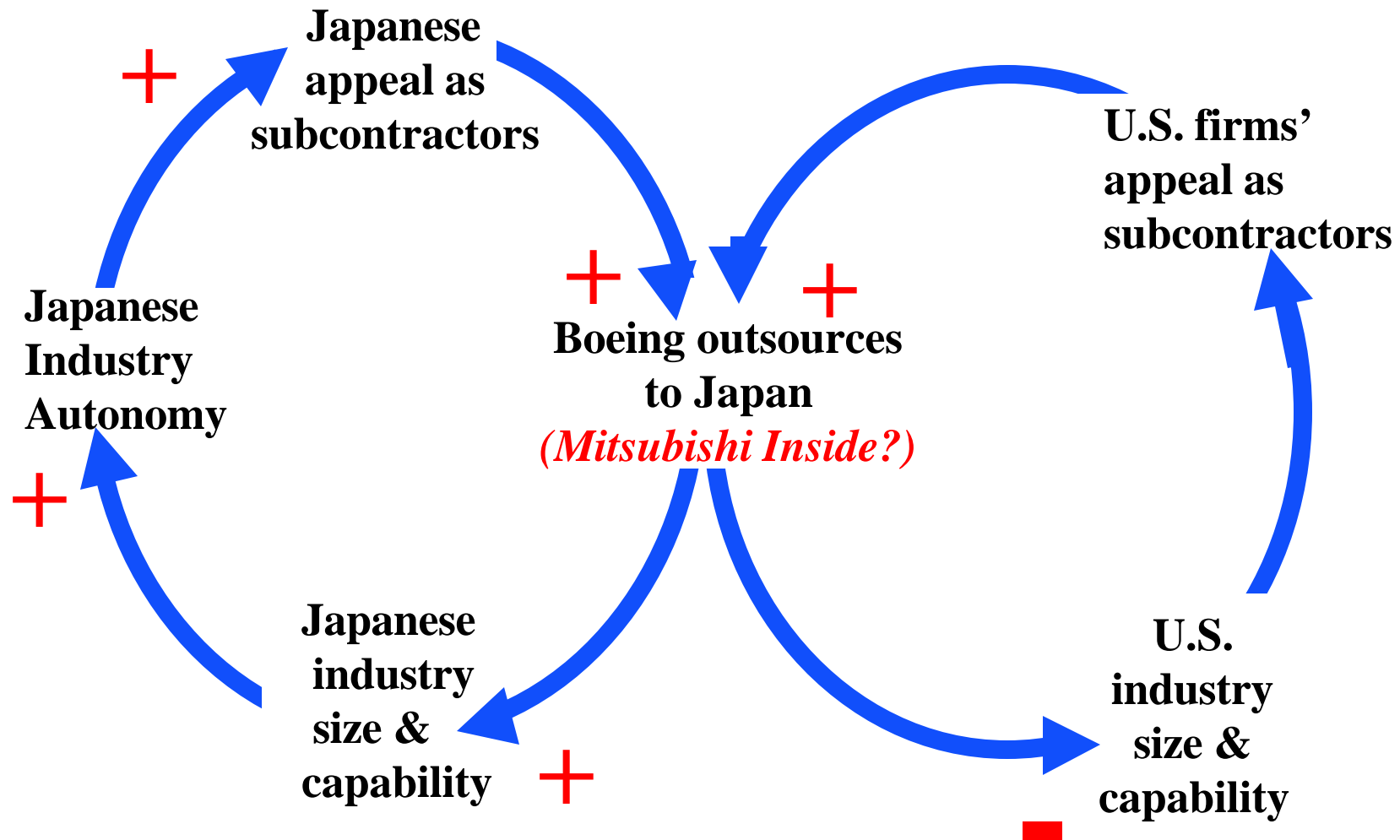
In/Outsourcing: Sowing the Seeds of Competence Development to develop dependence for knowledge or dependence for capacity

Prof C. Fine
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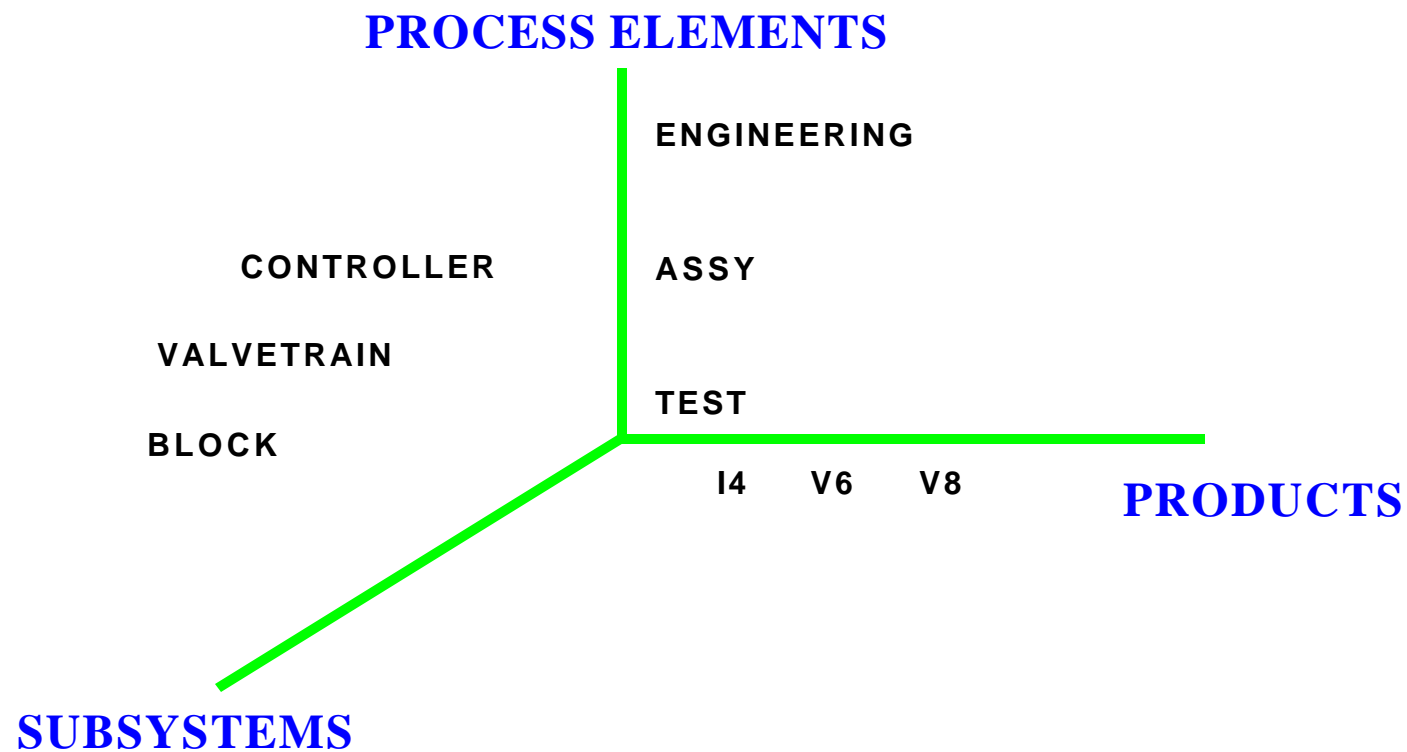
Technology Dynamics in the Aircraft Industry: LEARNING FROM THE DINOSAURS

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SOURCEABLE ELEMENTS

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Strategic Make/Buy Decisions: Assess Critical Knowledge & Product Architecture

Prof C. Fine

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	ITEM IS INTEGRAL ITEM IS MODULAR		
	DEPENDENT FOR KNOWLEDGE & CAPACITY	INDEPENDENT FOR KNOWLEDGE & DEPENDENT FOR CAPACITY	INDEPENDENT FOR KNOWLEDGE & CAPACITY
	A POTENTIAL OUTSOURCING TRAP	BEST OUTSOURCING OPPORTUNITY	OVERKILL IN VERTICAL INTEGRATION
	WORST OUTSOURCING SITUATION	CAN LIVE WITH OUTSOURCING	BEST INSOURCING SITUATION

Adapted from Fine & Whitney, "Is the Make/Buy Decision Process a Core Competence?"

Strategic Make/Buy Decisions:

Also consider Clockspeed & Supply Base Capability

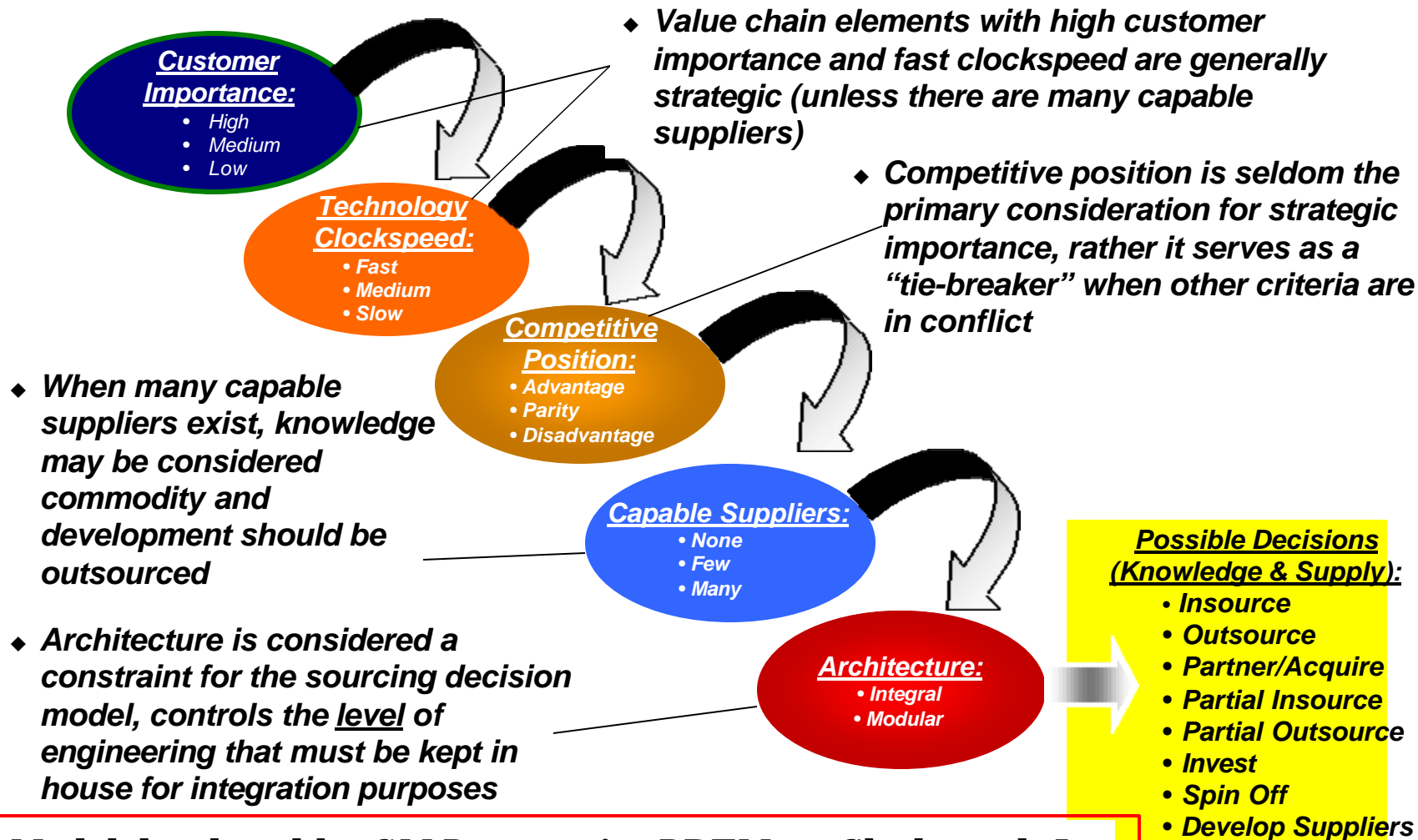
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		DEPENDENT FOR KNOWLEDGE & CAPACITY		DEPENDENT FOR CAPACITY ONLY		INDEPENDENT FOR KNOWLEDGE & CAPACITY								
DECOMPOSABLE (Modular)	Suppliers Few Many	Trap Clockspeed <i>Fast Slow</i>		Best Out Clockspeed <i>Fast Slow</i>		Over-kill Clockspeed <i>Fast Slow</i>								
		<table><tr><td></td><td><i>OK</i></td></tr><tr><td><i>Watch it!</i></td><td></td></tr></table>		<i>OK</i>	<i>Watch it!</i>		<table><tr><td></td><td></td></tr><tr><td></td><td></td></tr></table>					<table><tr><td></td><td></td></tr><tr><td></td><td></td></tr></table>		
	<i>OK</i>													
<i>Watch it!</i>														
INTEGRAL	Suppliers Few Many	Worst Clockspeed <i>Fast Slow</i>		OK Clockspeed <i>Fast Slow</i>		Best In Clockspeed <i>Fast Slow</i>								
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Adapted from C. Fine, *ClocksPEED*, Chap. 9

Qualitative analysis of strategic importance uses five key criteria

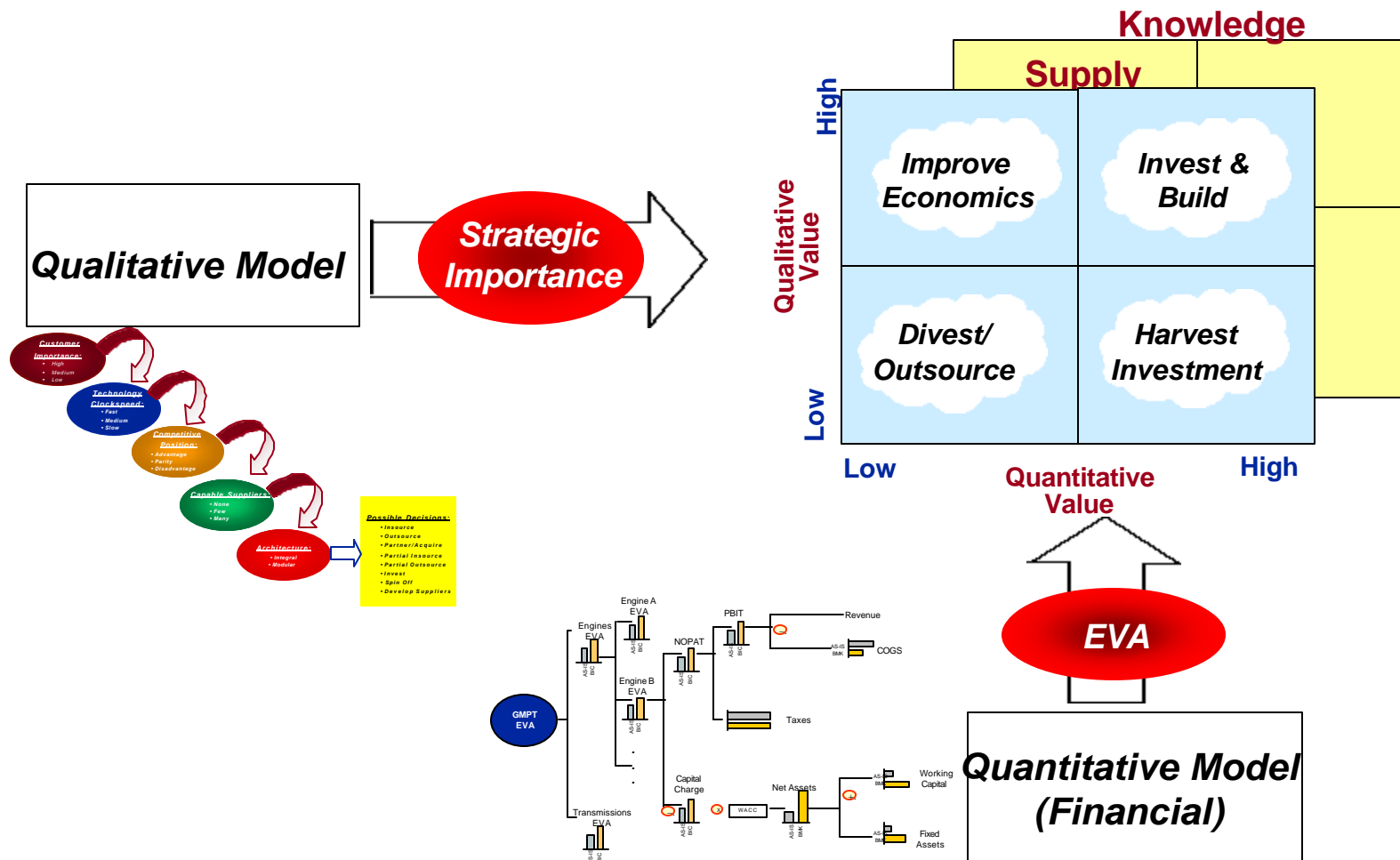
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Model developed by GM Powertrain, PRTM, & Clockspeed, Inc.

Every decision requires qualitative and quantitative analysis to reach a conclusion

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Model developed by GM Powertrain, PRTM, & Clockspeed, Inc.

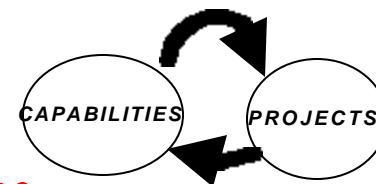
VALUE CHAIN DESIGN IS THE ULTIMATE CORE COMPETENCY

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Since *all advantages are temporary*,
the only lasting competency is to *continuously build and assemble capabilities chains*.

KEY SUB-COMPETENCIES:

1. **Forecasting the dynamic evolution** of market power and market opportunities
2. **Anticipating** Windows of Opportunity
3. **3-D Concurrent Engineering:**
Product, Process, Value Chain

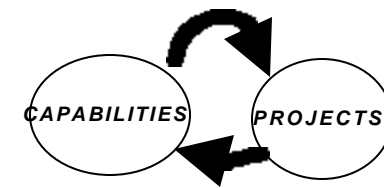
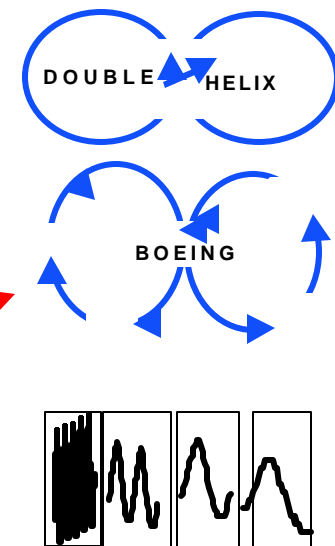


Fortune Favors the Prepared Firm

PROCESS FOR VALUE CHAIN DESIGN

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1. Benchmark the **Fruit Flies**
2. Map your Supply Chain
 - Organizational Value Chain
 - Technology Value Chain
 - Competence Chain
3. Dynamic Chain Analysis
at each node of each chain map
4. Identify **Windows of Opportunity**
5. Exploit **Competency Development Dynamics**
with **3-D Concurrent Engineering**



OPTICAL TELECOM VALUE CHAIN:

MINI CASE EXAMPLE

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NORTEL NETWORKS plays at at least three levels of the Optical Network Telecom value chain:

- Network design & installation
- Modules (OC-192 network elements)
- Components (lasers, amplifiers)

QUIZ: Should Nortel sell their components business?

Hint: How likely are the scenarios of:

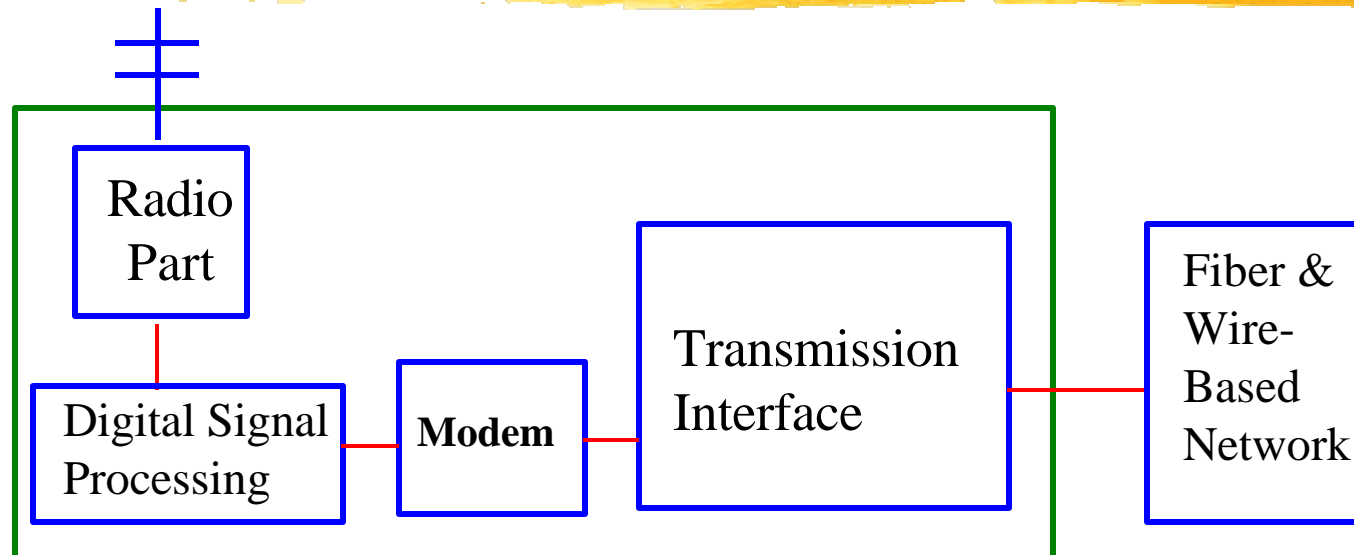
- An *Intel Inside* effect in components?
- Networks become sufficiently modular as to be assembled by the customer?

WIRELESS VALUE CHAIN: **MINI CASE EXAMPLE**

42

Wireless Base Stations (WSB'S) comprise 4 key subsystems:

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WSB architectures are
-integral & proprietary
Suppliers include: Nortel,
Moto, Ericsson, Siemens, Nokia
Disruptive Modem advances
(e.g., MUD) can double
Base Station Capacity

Modular WSB's might

- (1) Stimulate new WSB entrants (ala Dell)
- (2) Stimulate standard subsystem suppliers
- (3) lower prices to the network operators
- (4) Speed base station performance imp.
- (5) Increase demand for basestations due to improved price-performance ratios.

Roadmap Components: Dynamic Analyses

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- **Business cycle dynamics**
(e.g., systems dynamics-like models of the bullwhip effect)
- **Industry structure dynamics**
(e.g., double helix in *Clockspeed*)
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(Cross-National, Cross Sector)

Customer Preference Drivers

(adapted from Sadek Esener, UCSD and
Tom O'Brien, Dupont "Macro-Trends" process)

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- **Population**
 - Aging, Growth
- **Awareness**
 - of Environment/Energy costs, Personal Health
 - of consumption possibilities & disparities
- 3. Globalization**
 - of commerce, culture, knowledge, disease, terrorism
- 4. Clusters**
 - urbanization
 - wealth
 - affinity/ethnic groups
- 5. Technology**
 - cheap computation, pervasive connectivity
 - technology at the molecular (nano) level
(life sciences, electronics, polymers)

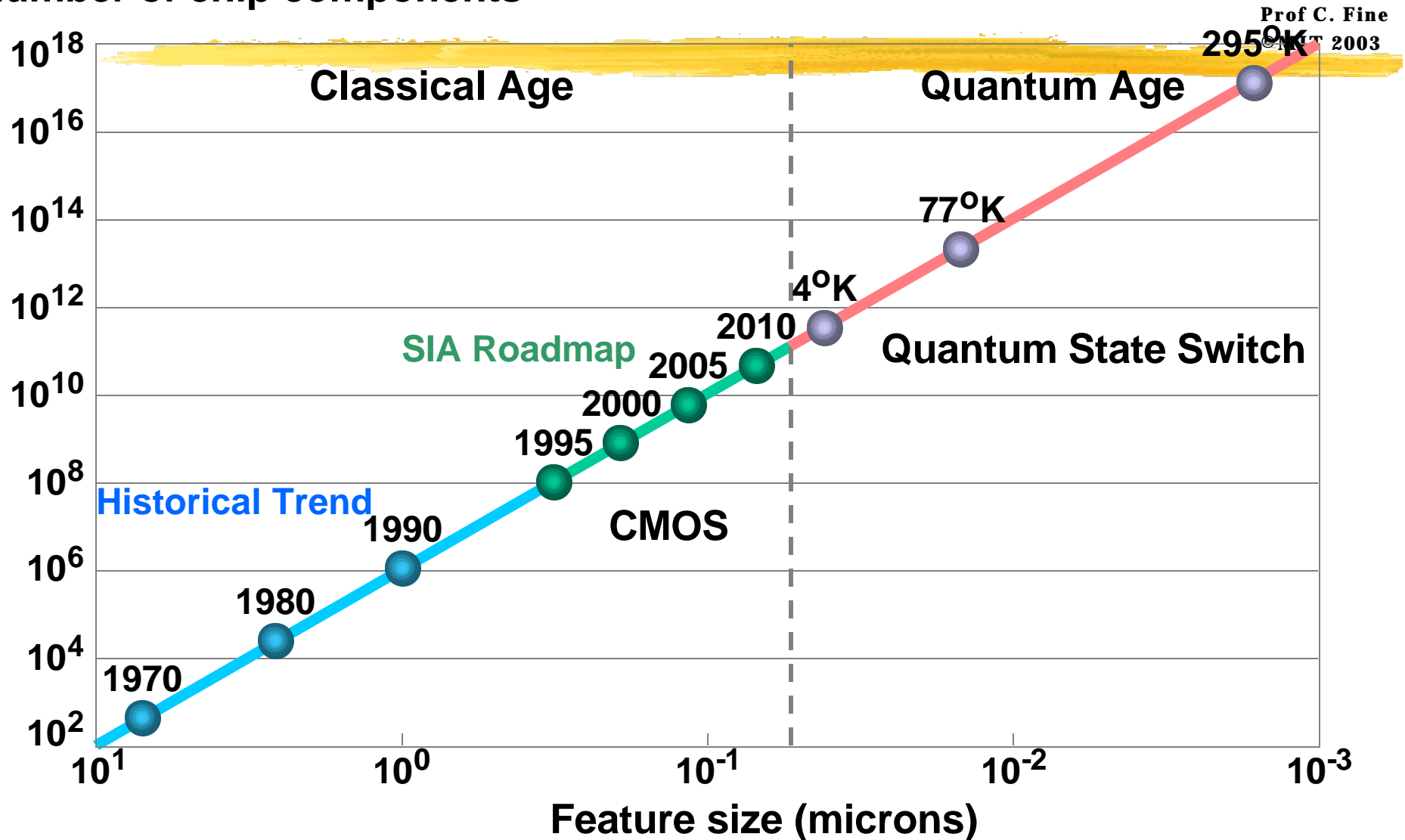
Roadmap Components: Dynamic Analyses

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(Cross-National, Cross Sector)

Roadmap for Electronic Devices

Number of chip components



Horst D. Simon

LAWRENCE BERKELEY NATIONAL LABORATORY

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MIT 2003

International Technology Roadmap for Semiconductors '99

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Year	2005	2008	2011	2014
Technology (nm)	100	70	50	35
DRAM chip area (mm ²)	526	603	691	792
DRAM capacity (Gb)	8		64	
MPU chip area (mm ²)	622	713	817	937
MPU transistors (x10 ⁹)	0.9	2.5	7.0	20.0
MPU Clock Rate (GHz)	3.5	6.0	10.0	13.5

Disk Drive Development 1978-1991

48

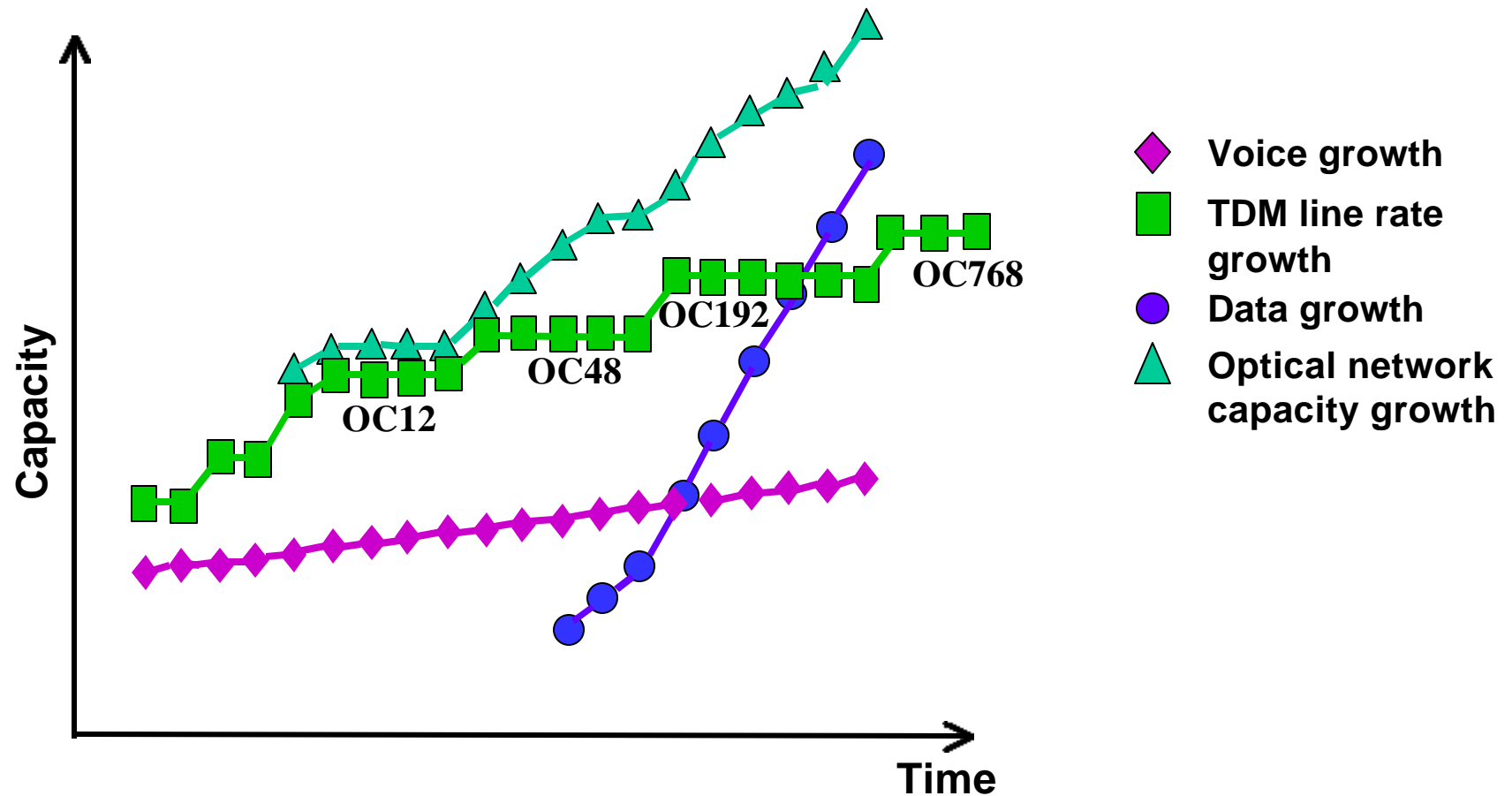
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Disk Drive Generation	Dominant Producer	Dominant Usage	Approx cost per Megabyte
14"	IBM	mainframe	\$750
8"	Quantum	Mini-computer	\$100
5.25"	Seagate	Desktop PC	\$30
3.5"	Conner	Portable PC	\$7
2.5"	Conner	Notebook PC	\$2

From 1991-98, Disk Drive storage density increased by 60%/year while semiconductor density grew ~50%/year. Disk Drive cost per megabyte in 1997 was ~ \$.10

Optical Networking is Keeping Up!

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"Killer Technologies" of the Information Age: Semiconductors, Magnetic Memory, Optoelectronics

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“We define a ‘killer technology’ as one that delivers enhanced systems performance of a factor of at least a hundred-fold per decade.”

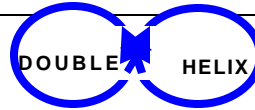
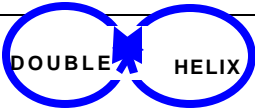
C.H.Fine & L.K. Kimerling, "Biography of a Killer Technology: Optoelectronics Drives Industrial Growth with the Speed of Light," published in 1997 by the Optoelectronics Industry Development Association, 2010 Mass Ave, NW, Suite 200, Wash. DC 20036-1023.

Killer Question:

Will Integrated Optics evolve linearly like Semiconductors with Moore's Law or like Disk Drives with repeated industry disruptions?

Optical Technology Evolution: Navigating the Generations with an Immature Technology

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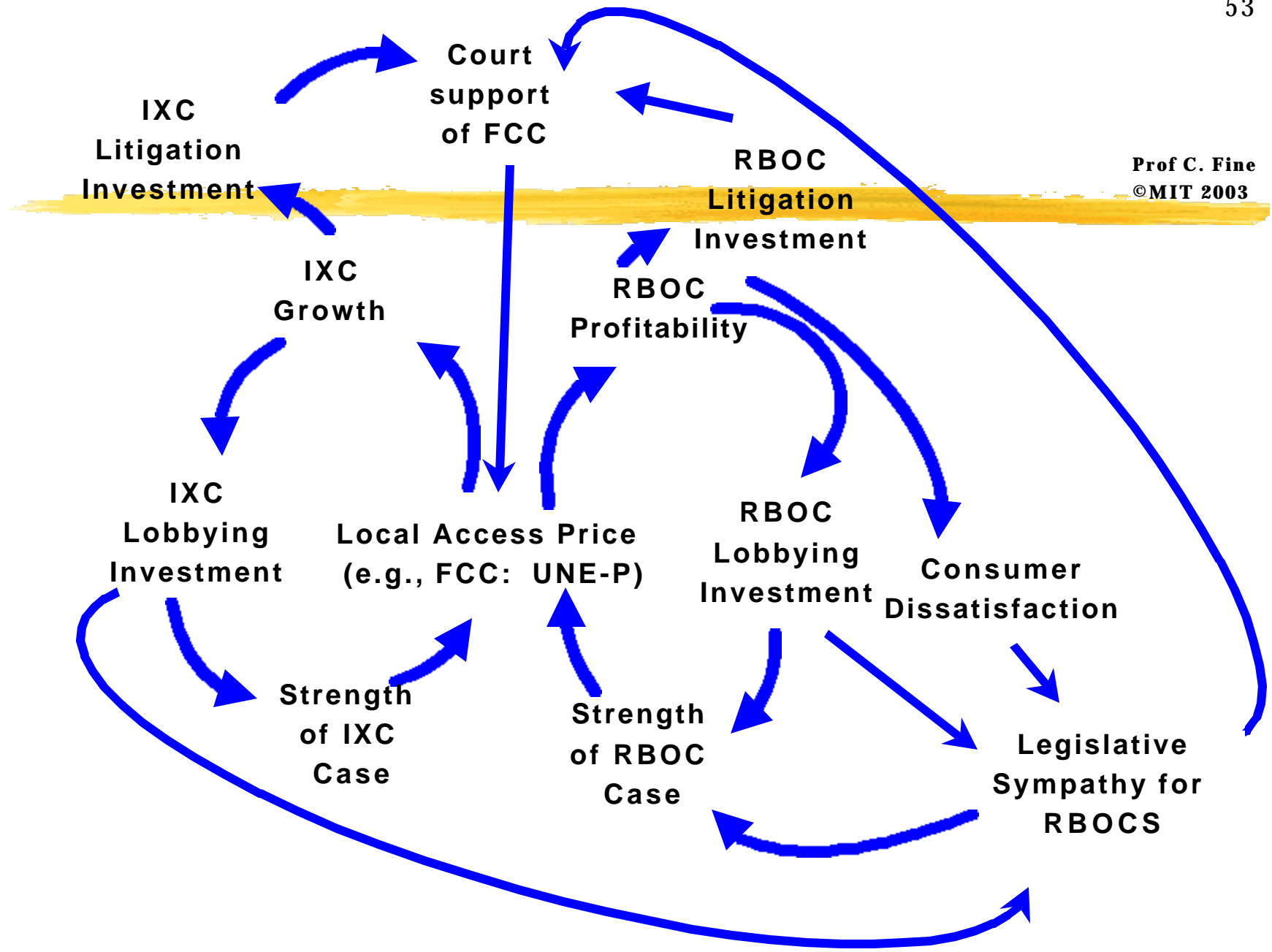
	1	2	3	4	5
Timeline	Now	Starting	Starting	3-5 years	5-15 years
Stage	Discrete Components	Hybrid Integration	Low-level monolithic integration	Medium Monolithic integration	High-level monolithic integration
Examples	MUX/ DEMUX	TX/RX module OADM	TX/RX module OADM	OADM, Transponder Switch Matrix	Transponder
Core Technologies	FBGs, Thin-film, fused fiber, mirrors	Silicon Bench, Ceramic substrates	Silica Silicon InP	InP, ??	InP, ??
How many Functions?	1	2-5	2-5	5-10	10-XXX
Industry Structure	Integrated	Integrated/ Horizontal	Integrated /Horizontal		

Dr. Yanming Liu, MIT & Corning

Roadmap Components: Dynamic Analyses

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- **Business cycle dynamics**
(e.g., systems dynamics-like models of the bullwhip effect)
- **Industry structure dynamics**
(e.g., double helix in *Clockspeed*)
- 3. **Corporate strategy dynamics** (e.g., dynamic matching of customer needs with corporate opportunities)
- 4. **Customer Preference Dynamics**
- 5. **Technology dynamics** (e.g., the Semiconductor Industry Assoc. roadmap built around Moore's law)
- 6. **Regulatory Policy Dynamics**
(Cross-National, Cross Sector)



All Conclusions are *Temporary*

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Clocks speeds are increasing almost everywhere
Value Chains are changing rapidly

